ASM Pacific Technology

2020 Interim Results Announcement

29 July 2020

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Awards & Accolades

Forbes Asia
2019
BEST OVER
A BILLION

2019
HKMA
Quality
Award
GRAND
AWARD

SINGAPORE
QUALITY
AWARD
2019 WINNER

Winner of the
productronica
innovation award 2019

ASIA'S OUTSTANDING
COMPANIES
POLL
2019
ASIAMONEY

VLSIresearch
RANKED
1st
SUPPLIERS
Customer Satisfaction
2019

VLSIresearch
THE BEST
SUPPLIERS
Customer Satisfaction
2019

VLSIresearch
10 BEST
SUPPLIERS
Customer Satisfaction
2019

HKC
香港企業公民

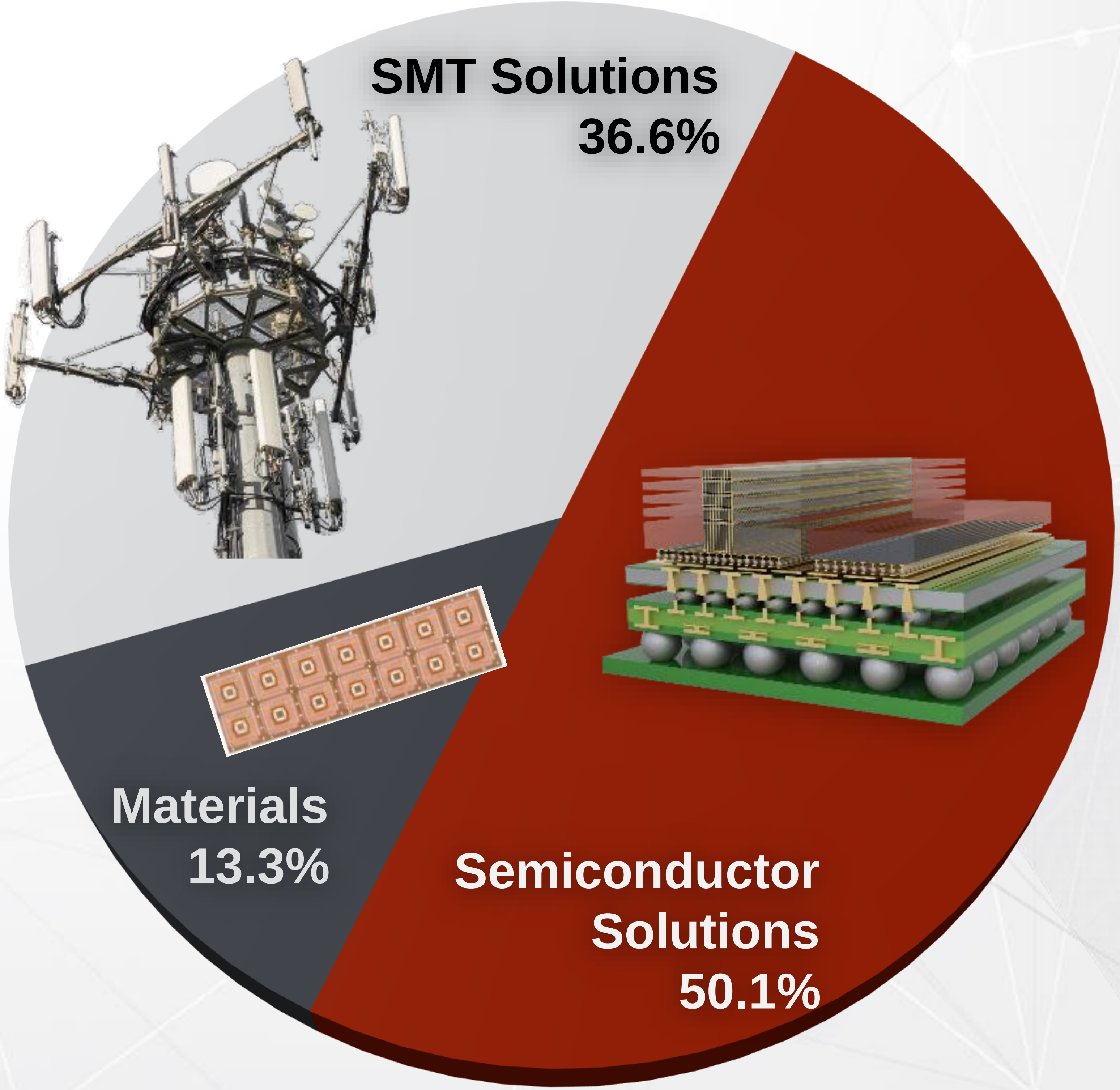
BEST HR AWARDS 2019

香港恒生大學
2019(第九屆) 君子企業計劃
IN PURSUIT OF THE JUNZI SPIRIT

The World's Technology & Market Leader

Q2 2020 Group Revenue:

USD 557m



ASM Pacific Technology

2018 THOMSON REUTERS TOP100 GLOBAL TECH LEADER

ASMPT'S **Major Facilities** Around The World

● Sales Offices

● Business Centre / R&D / Manufacturing Site

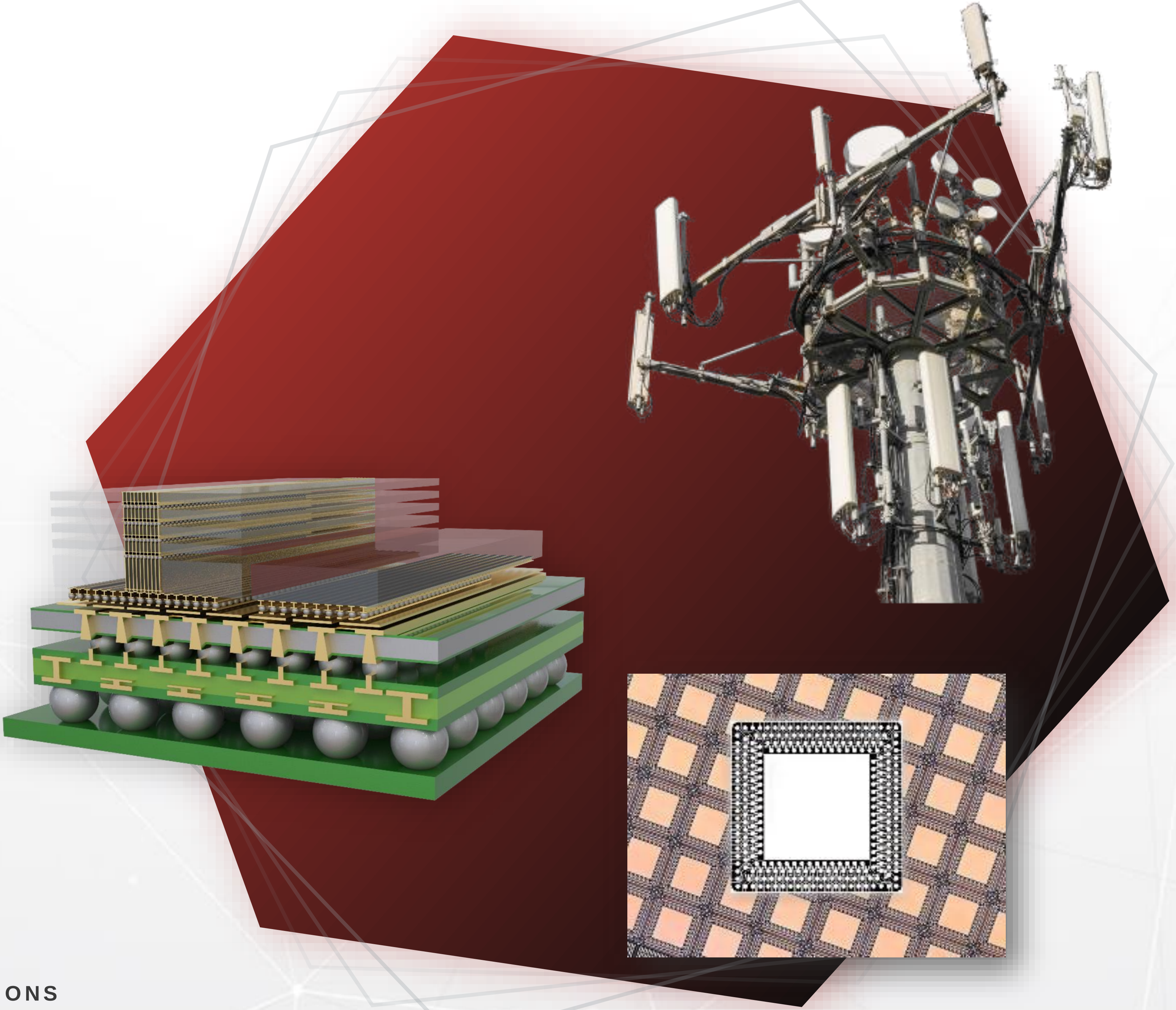
>2,000 Global R&D staff

>1,400 Patents on leading edge technologies

10 R&D centres worldwide

12 Manufacturing facilities

Three Business Segments With
Leading Market Positions



SEMICONDUCTOR SOLUTIONS[1]

#1 in Assembly & Packaging Equipment Market

Since 2002

2019 Worldwide
PAE Market Share:

~29%

SMT SOLUTIONS

#2 in SMT Equipment Market

2019 Worldwide
SMT Market Share:

~22%

MATERIALS

#3 in Leadframe Market

2018 Worldwide
Leadframe Market Share:

~9%

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[1] FORMERLY BACKEND EQUIPMENT SOLUTIONS

Sources: VLSI, SEMI and ASMPT Market Intelligence |

Our Strategic Value-added Acquisitions

Advanced Packaging

NEXX systems

- Largest installed base of panel deposition tools
- Addition to the Advanced Packaging suite of solutions
- High Performance Computing (HPC)

Silicon Photonics

AMICRA microtechnologies

- Ultra high precision sub-micron die attach equipment solutions
- In prime position to capture demand for future data centre bandwidth growth and next generation 5G deployments

Manufacturing Execution Software

Critical manufacturing

- Provider of automation and manufacturing software for high-tech industries
- Capture demand for SMART Factory software solutions

SKTMAX 深科特

- Well-established MES solutions provider with a strong presence in China.
- Complements Critical Manufacturing MES solutions, reinforcing ASMPT's position in the China market.

Our Participation in Emerging and Disruptive Technologies

Minority Investments in Start-ups

X-ray Inspection

- X-ray inspection of advanced semiconductor packages
- Up to 100X faster vs conventional X-ray using proprietary technology

3D Laser Printing

- Israeli company with cutting-edge technology
- Potentially disruptive technology to the SMT printing industry

Strategic Collaborations

Data Analytics

sas

- Industrial IoT Solutions to deliver holistic data analytics solutions
- Provide customer value through productivity, quality and reliability in manufacturing operations

AI Chip Technology

IBM **Research**

- Development of Heterogeneous Integration (HI) to advance packaging technologies and tools

2020 Q2 Highlights

Q2/1H 2020 Billings

	Q2			1H		
	USD	QoQ	YoY	USD	HoH	YoY
Group	557m	+27.8%	+19.5%	992m	-10.5%	+5.9%
Semi Solutions Segment	279m	+43.0%	+33.8%	473m	-4.5%	+16.6%
Materials Segment	74m	+43.2%	+28.2%	126m	-3.2%	+15.6%
SMT Solutions Segment	204m	+8.0%	+2.2%	393m	-18.7%	-6.9%

Group

- 1H Group Billings ~US$1B
  - ▲ 5.9% YoY ▼ 10.5% HoH
- Q2 Group Billings
  - ▲ 19.5% YoY ▲ 27.8% QoQ

SEMI

Key drivers for Q2 YoY billings growth

- Advanced Packaging
  - NEXX delivered strong growth
- Other drivers: Optoelectronics and IC/Discrete
- Traditional wire/die bonders delivered relatively strong growth
- CIS billings relatively weaker due to soft smartphone market demand

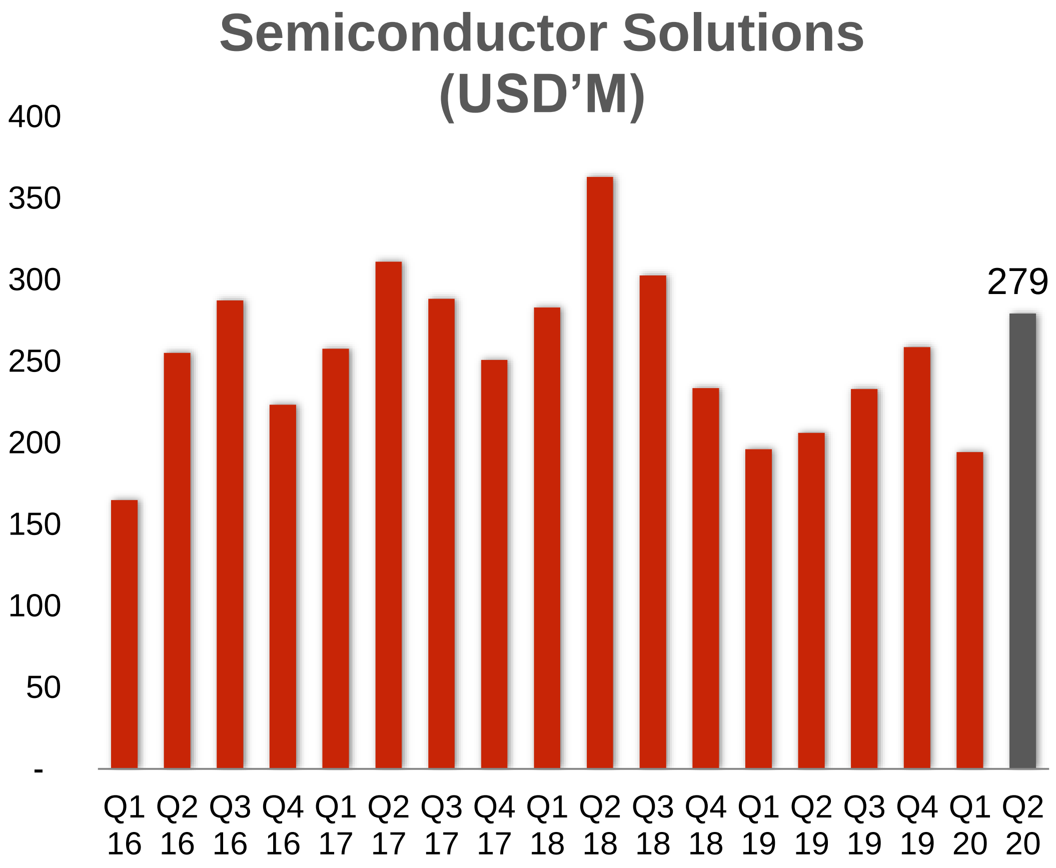
SMT

- Driven by 5G & SiP applications

Q2 2020 Billings – Business Segments

QoQ Growth:

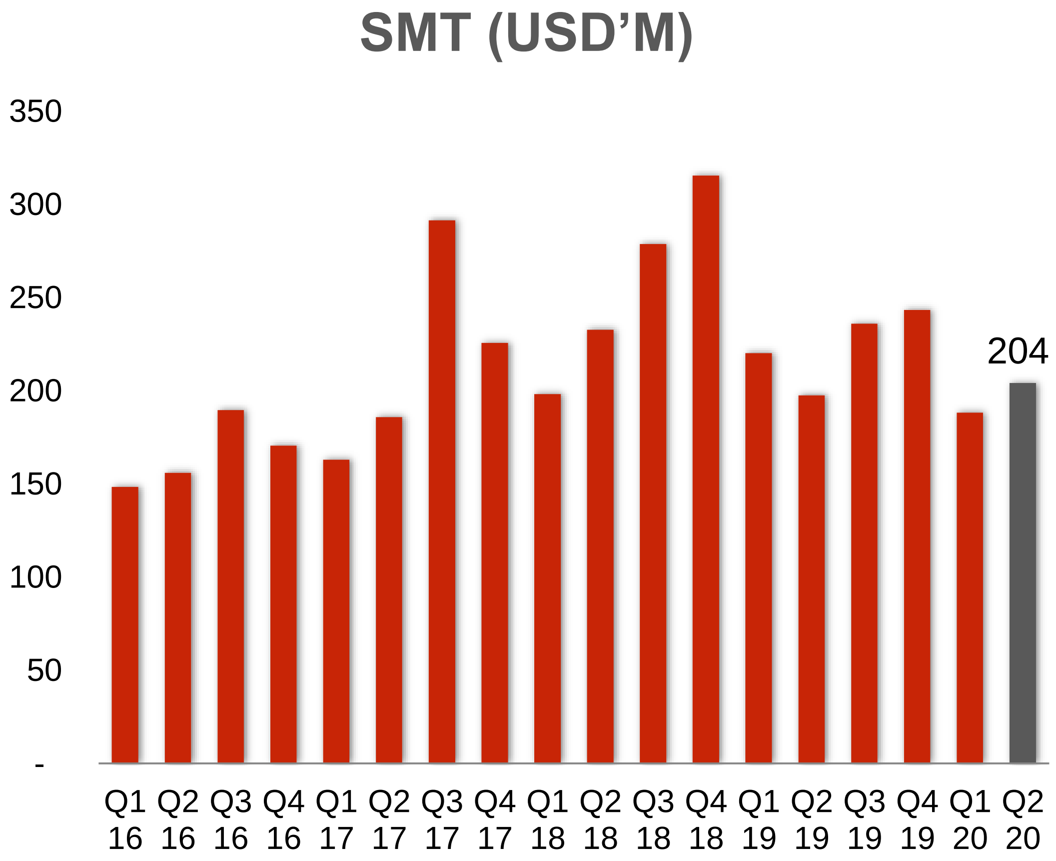
+43.0%



Semiconductor Solutions (USD'M)

QoQ Growth:

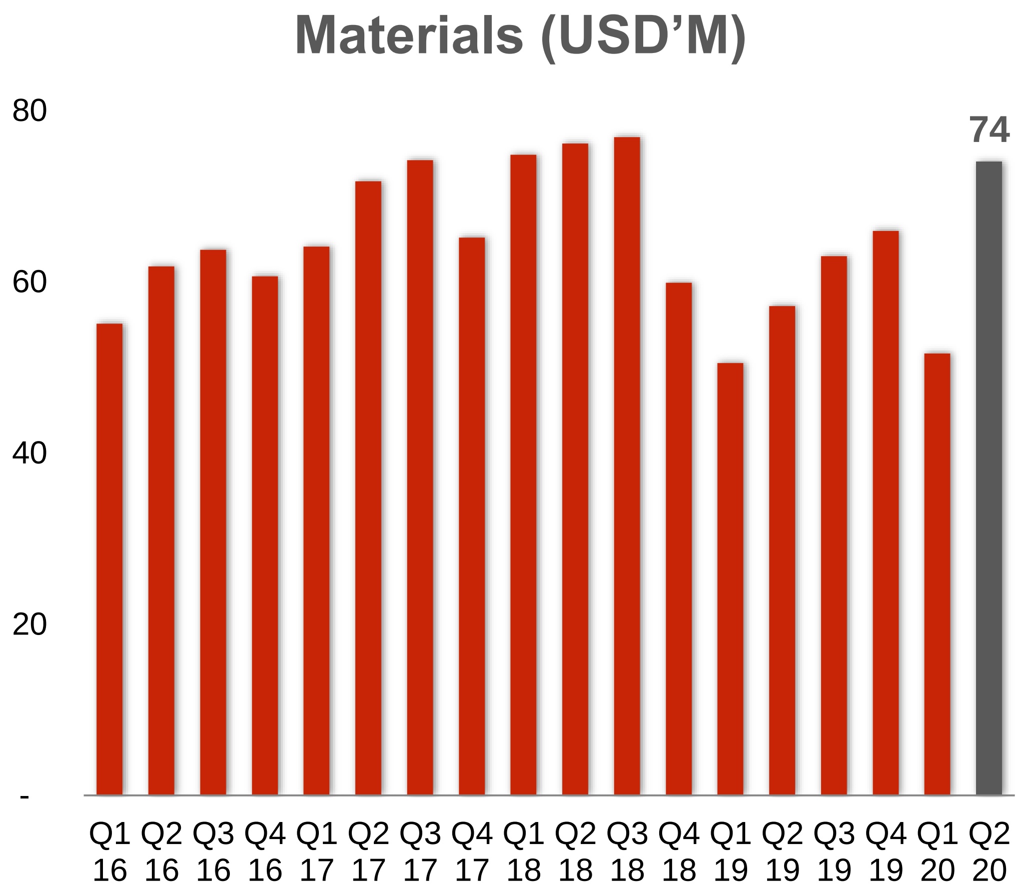
+8.0%



SMT (USD'M)

QoQ Growth:

+43.2%



Materials (USD'M)

Q2/1H 2020 Group Bookings

	Q2			1H		
	USD	QoQ	YoY	USD	HoH	YoY
Group	472m	-29.4%	-21.6%	1,141m	+19.0%	+7.4%
Semi Solutions Segment	227m	-26.7%	-8.1%	537m	+21.7%	+14.2%
Materials Segment	78m	-11.8%	+32.7%	167m	+25.2%	+59.3%
SMT Solutions Segment	167m	-38.4%	-43.7%	437m	+13.7%	-10.3%

Group

- 1H Bookings ▲ HoH and YoY
- Q2 Bookings ▼ QoQ and YoY as a result of overall weak sentiment due to COVID-19

SEMI

- Q2 Bookings ▼ QoQ due to higher Q1 base
- Key drivers of Q2 Bookings
  - Advanced Packaging
  - Optoelectronics and IC/Discrete
- Q2 Bookings for CIS relatively weaker due to soft smartphone market

SMT

- Key driver of Q2 Bookings
  - 5G-related investments in China
  - SiP
- Q2 Bookings in Automotive and Industrial Applications were weak

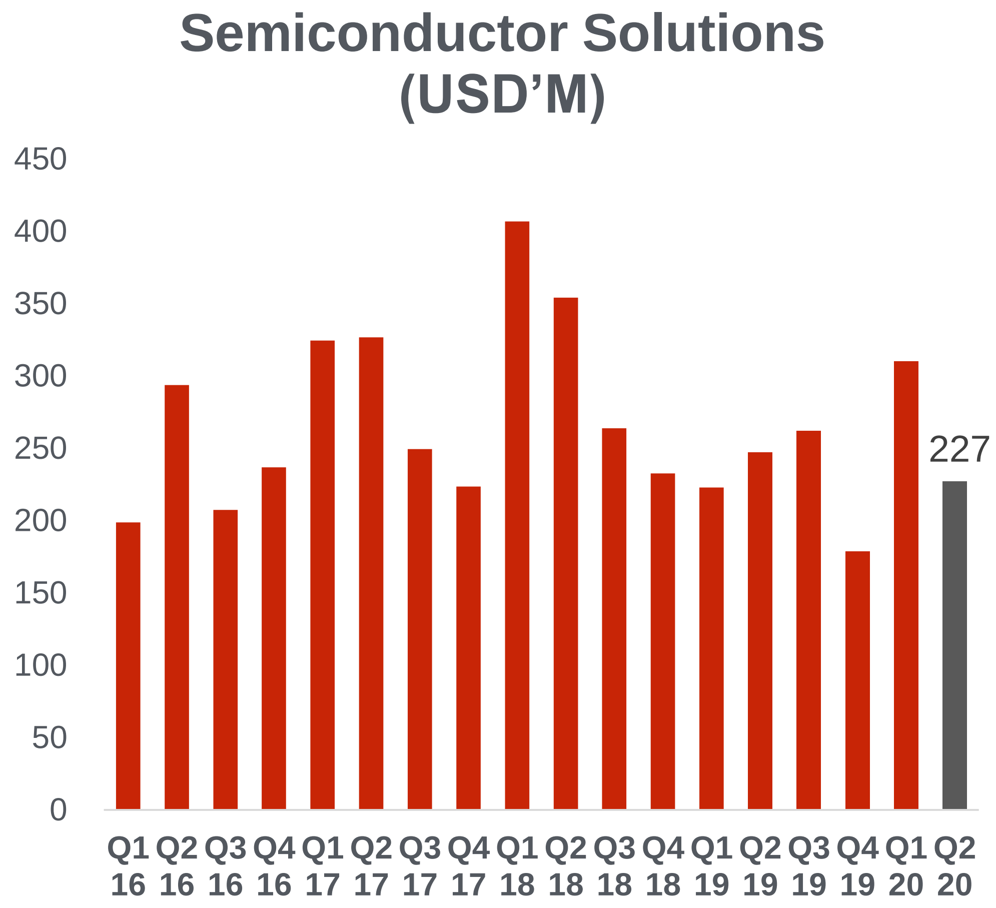
Materials

- Q2 Bookings at high level despite decline QoQ after 5 consecutive quarters' growth

Q2 2020 Bookings – Business Segments

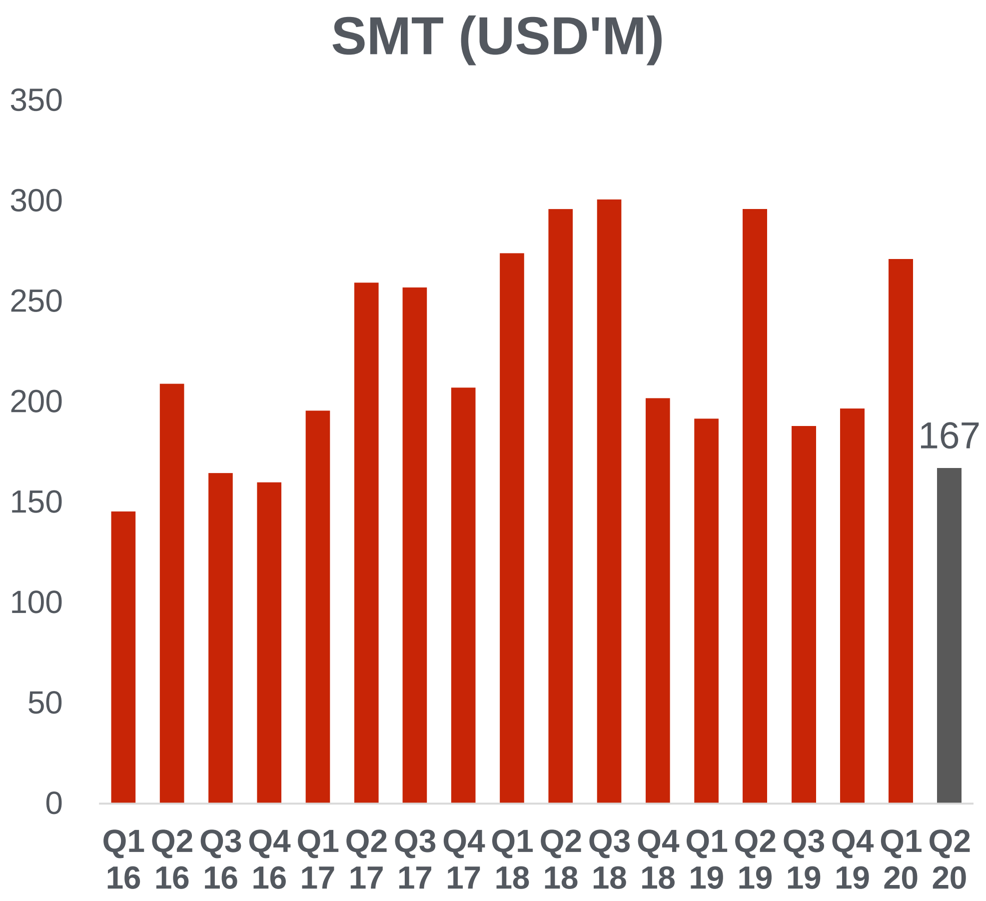
QoQ Growth:

-26.7%



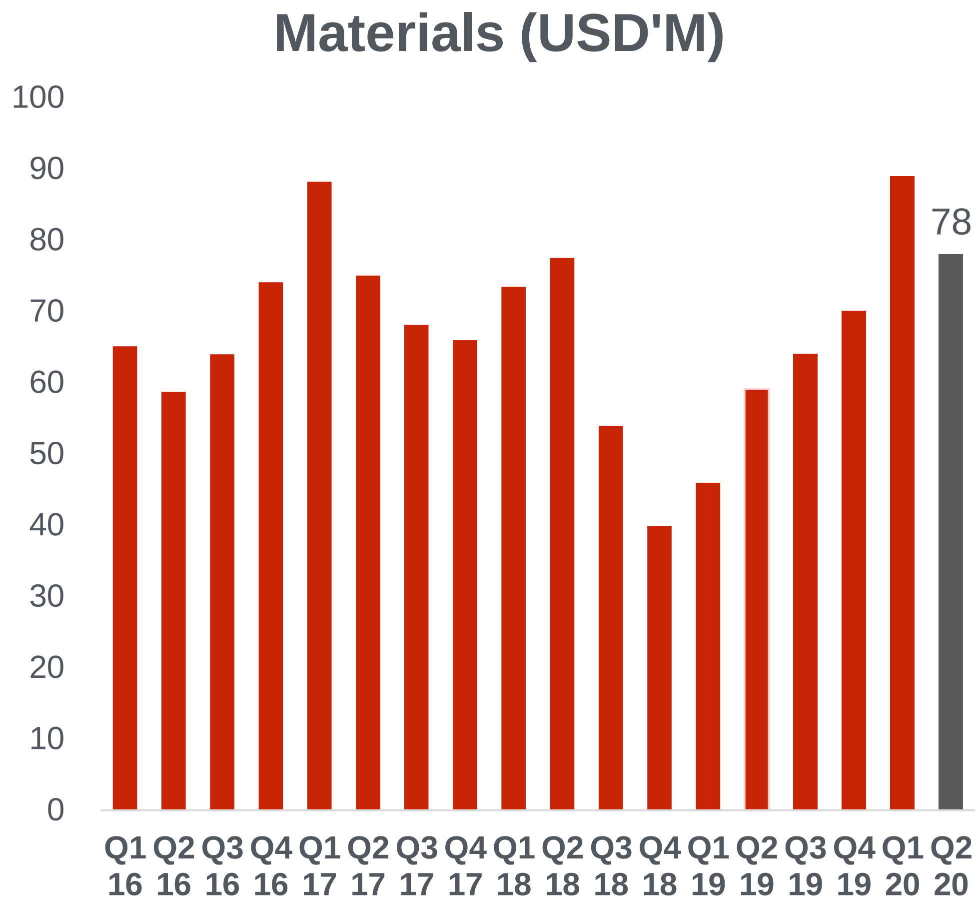
QoQ Growth:

-38.4%



QoQ Growth:

-11.8%



2018 THOMSON REUTERS TOP100 GLOBAL TECH LEADER

Q2/1H 2020 Group GM & Profitability

Gross Margin	1H	HoH	YoY		Q2	QoQ	YoY
Group	34.5%	-29 bps	-34 bps		35.2%	+169 bps	-54 bps
Semi Solutions Segment	42.2%	+16bps	+219 bps		42.9%	+162 bps	+211 bps
Materials Segment	13.5%	+409 bps	+250 bps		16.9%	+838 bps	+546 bps
SMT Solutions Segment	31.8%	-225 bps	-409 bps		31.3%	-101 bps	-616 bps
Group Billing (USD)	992m	-10.5%	+5.9%		557m	+27.8%	+19.5%
Operating Profit (HKD)	641m	-16.7%	+30.2%		496m	+241.1%	+95.8%
Net Profit (HKD)	391m	-12.0%	+119.2%		365m	+1,341.5%	+421.8%

Group

- Q2 Group GM close to mid-point of guidance
- Q2 Group Billing, Operating Profit and Net Profit ▲ QoQ and YoY

SEMI

- 1H GM ▲ YoY due to higher volume effect, increased productivity, product mix and cost reduction efforts

SMT

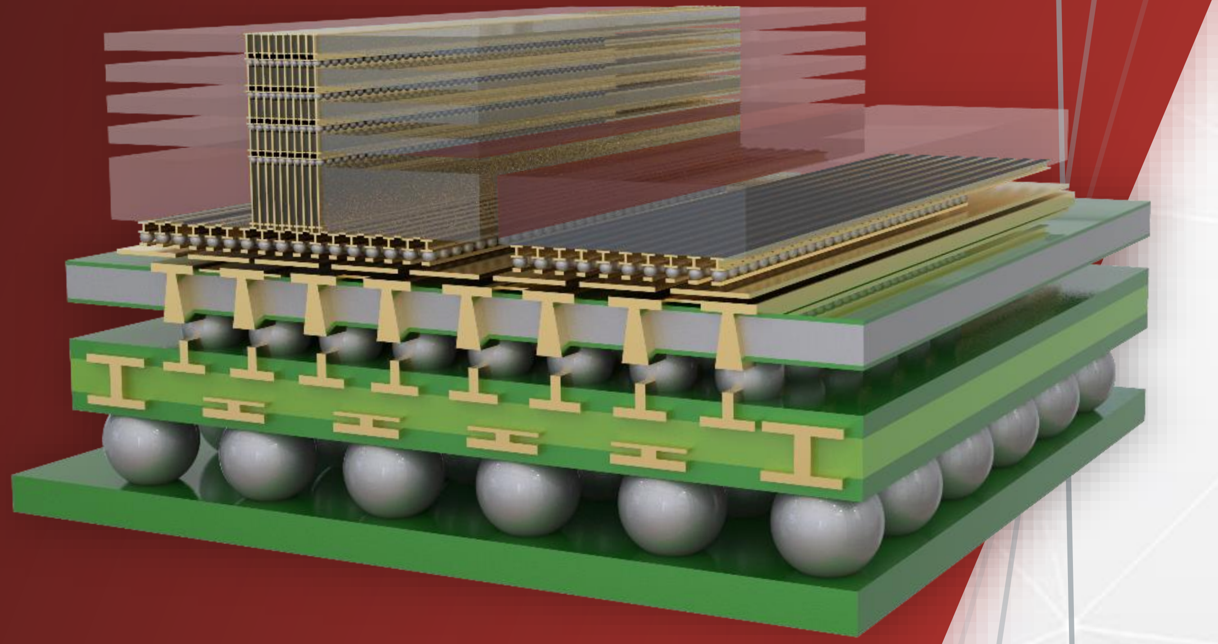
- 1H GM ▼ YoY due to lower contribution from Automotive and Industrial Applications; and larger China customer base

Materials

- 1H GM ▲ YoY due to higher volume effect and discontinuation of loss-making MIS business

Key Highlights:

1H YoY Bookings Growth:
+14.2%



Semiconductor Solutions Segment

- Strong global demand for HPC for datacentre and 5G applications
    - Q2 Billings growth YoY underpinned by Advanced Packaging
    - Q2 NEXX Bookings ▲ ~100% YoY
- Largest installed base to-date worldwide for Thermo-Compression Bonding (TCB) solutions
- NEXX has largest installation of panel plating tools for HPC applications
- Frontier-focused joint development with IBM Research on integrated solutions for HI, using ALSI Laser dicing, Hybrid Bonding and other AP interconnect tools

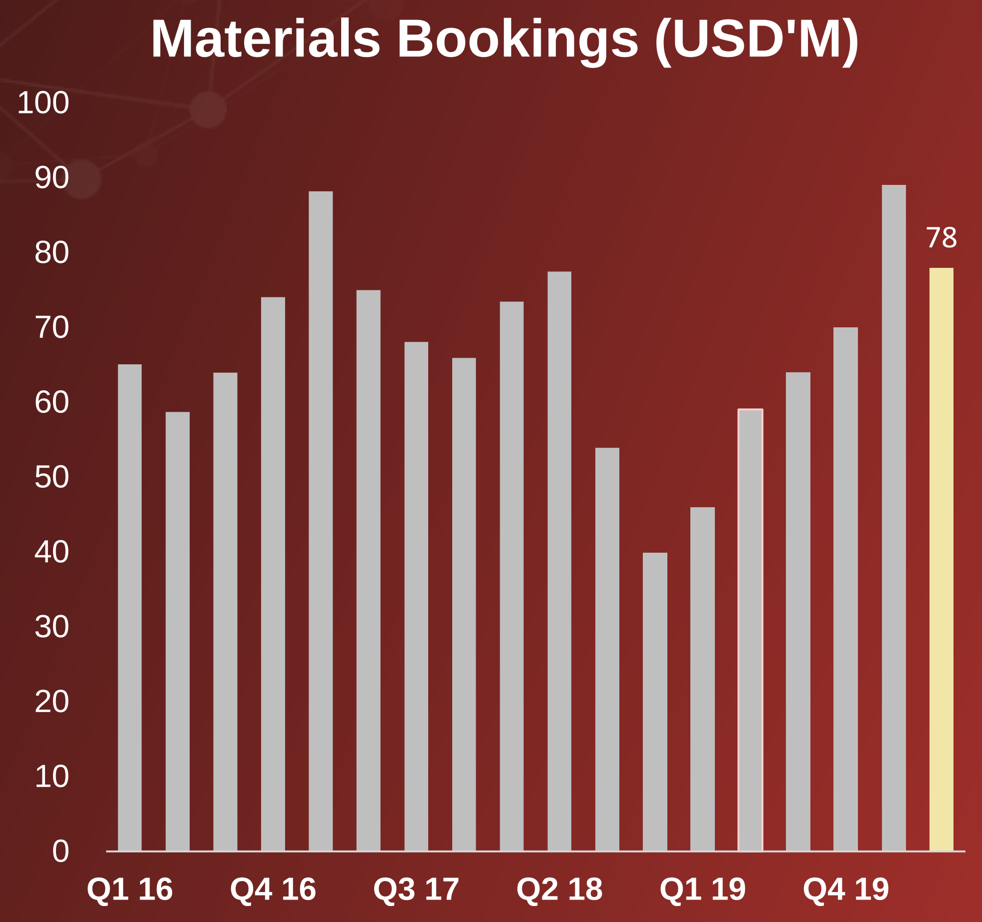
1H YoY Bookings Growth:
-10.3%

Key Highlights:

SMT Segment

- Market leader in System-in-Packaging (SiP)
- 1H booking momentum driven by
  - 5G-related investments
  - SiP – fast growing business within SMT

1H YoY Bookings Growth: +59.3%

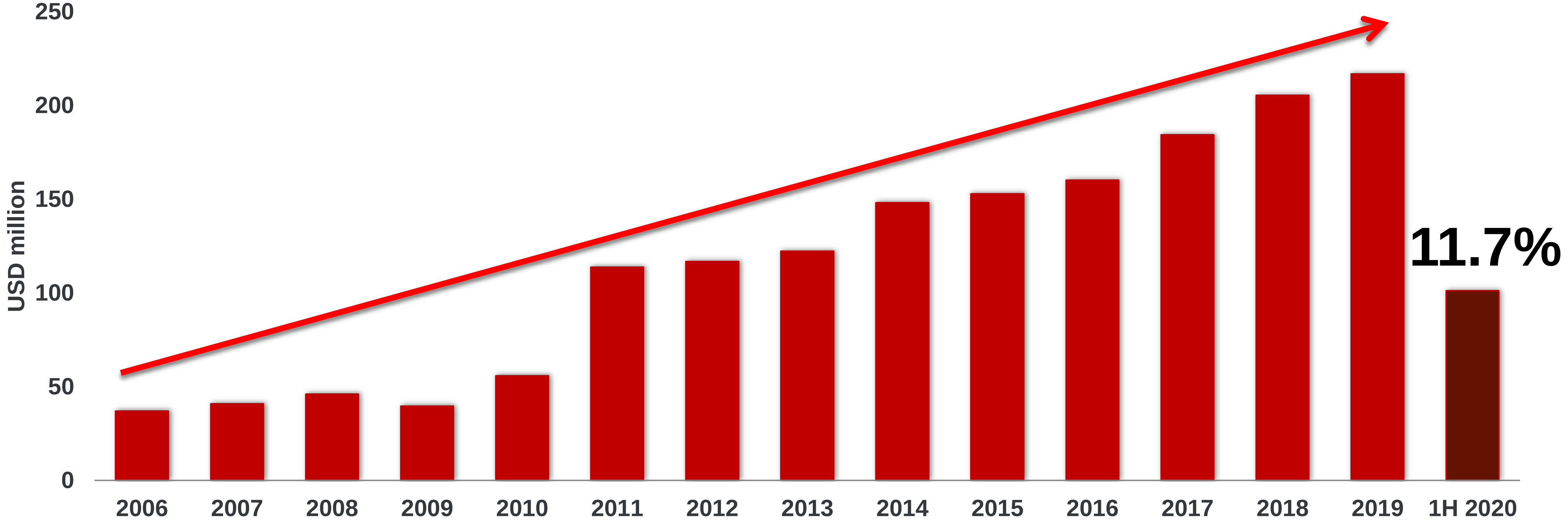

Materials Bookings (USD'M)

Key Highlights:

Materials Segment

- Segment new bookings increased five out of the last six quarters
- GM improvements resulted from higher volume effect and discontinuation of loss-making MIS business
- High level of Q2 Bookings indicates healthy demand for semiconductor devices
- Strategic JV expected to bring Materials Business to greater heights

R&D Commitment Makes Us a Preferred Partner of Choice



USD1,742 million invested in R&D

1H 2020 R&D expenditure

- US$ 101 million
- 11.7% of Equipment Sales

Package Interconnection

Optics precision engineering

Vibration control

Laser dicing & grooving

SMT

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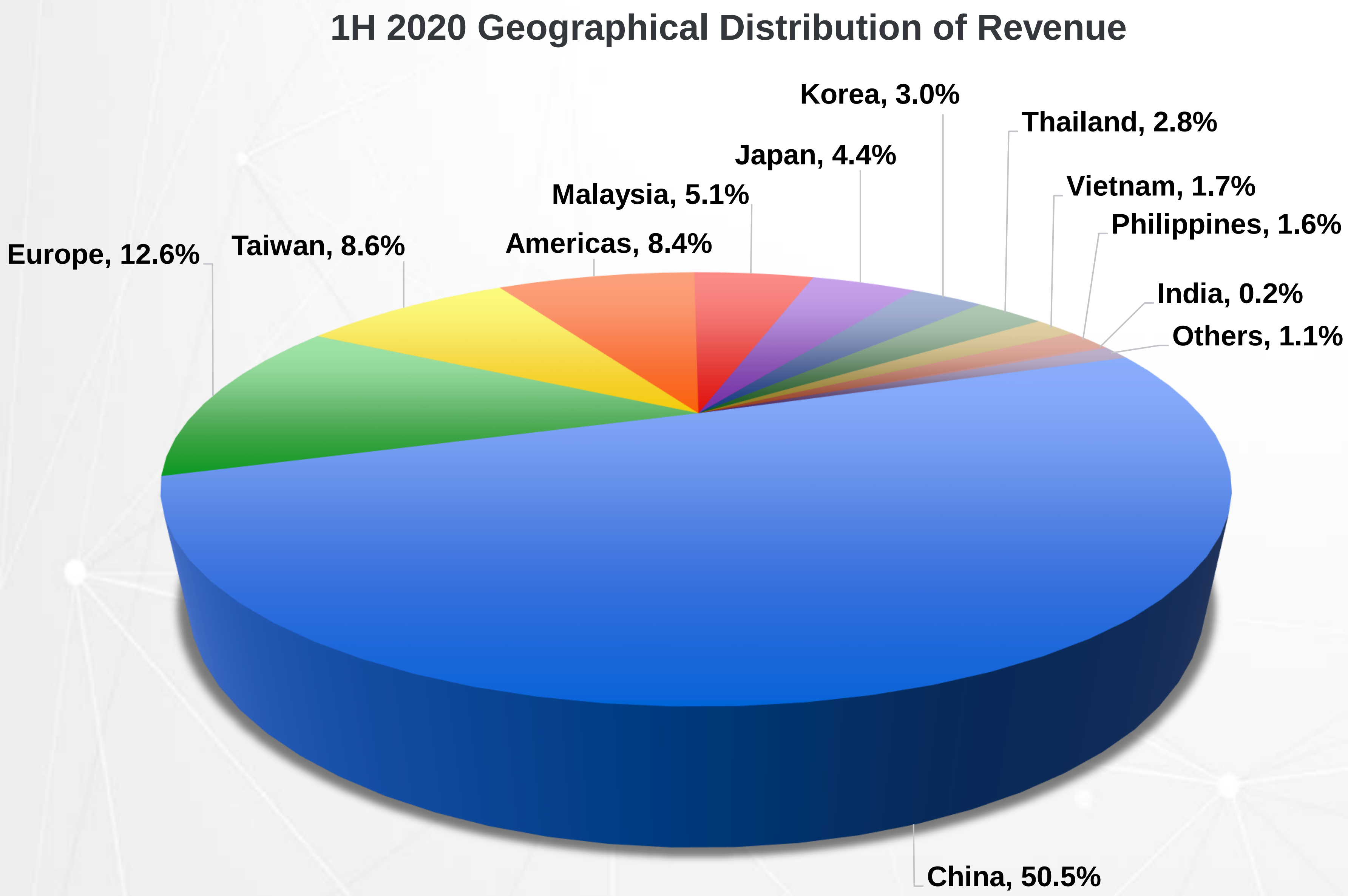
2018 THOMSON REUTERS TOP100 GLOBAL TECH LEADER

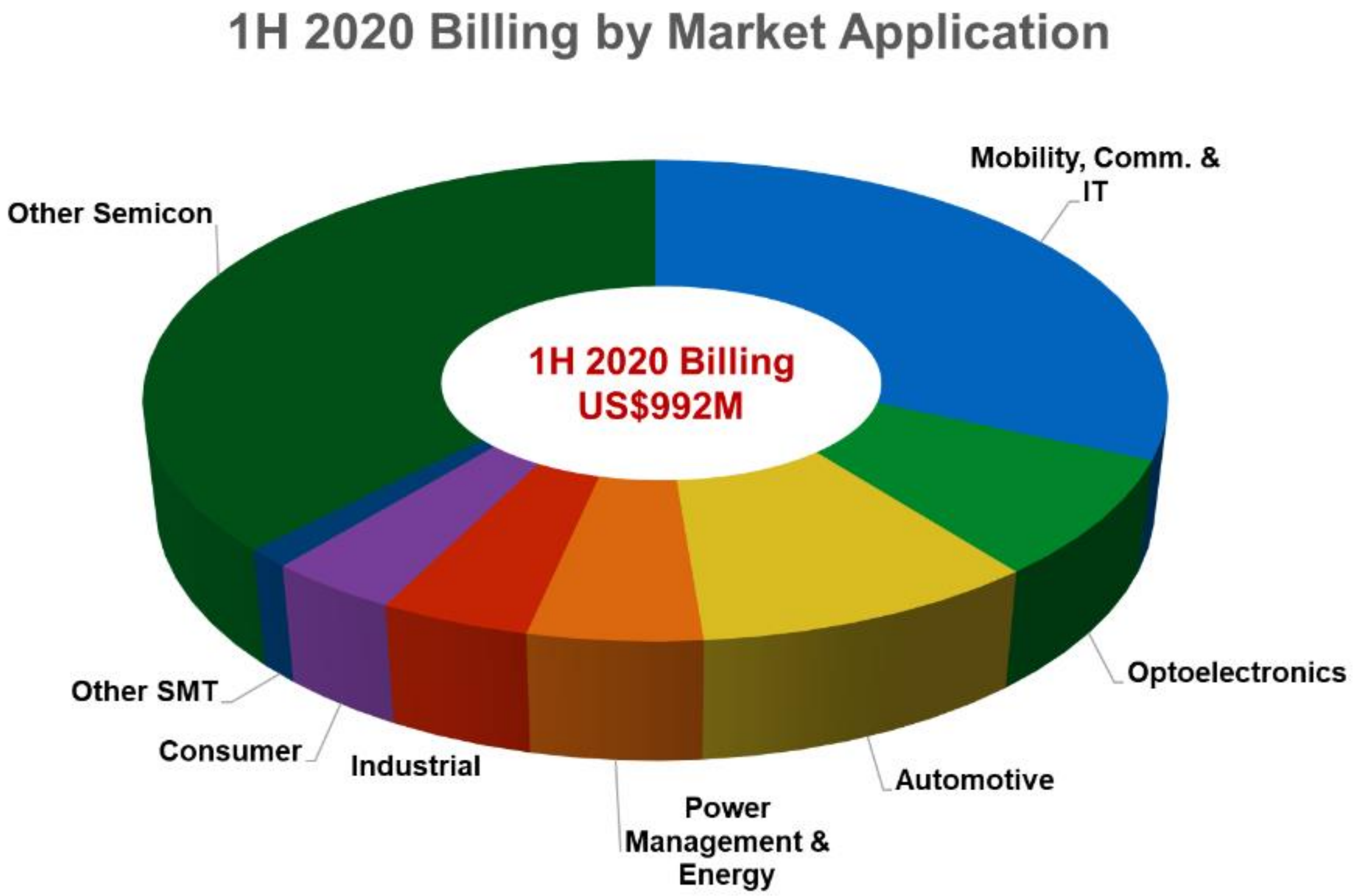
An Extensive Customer Base



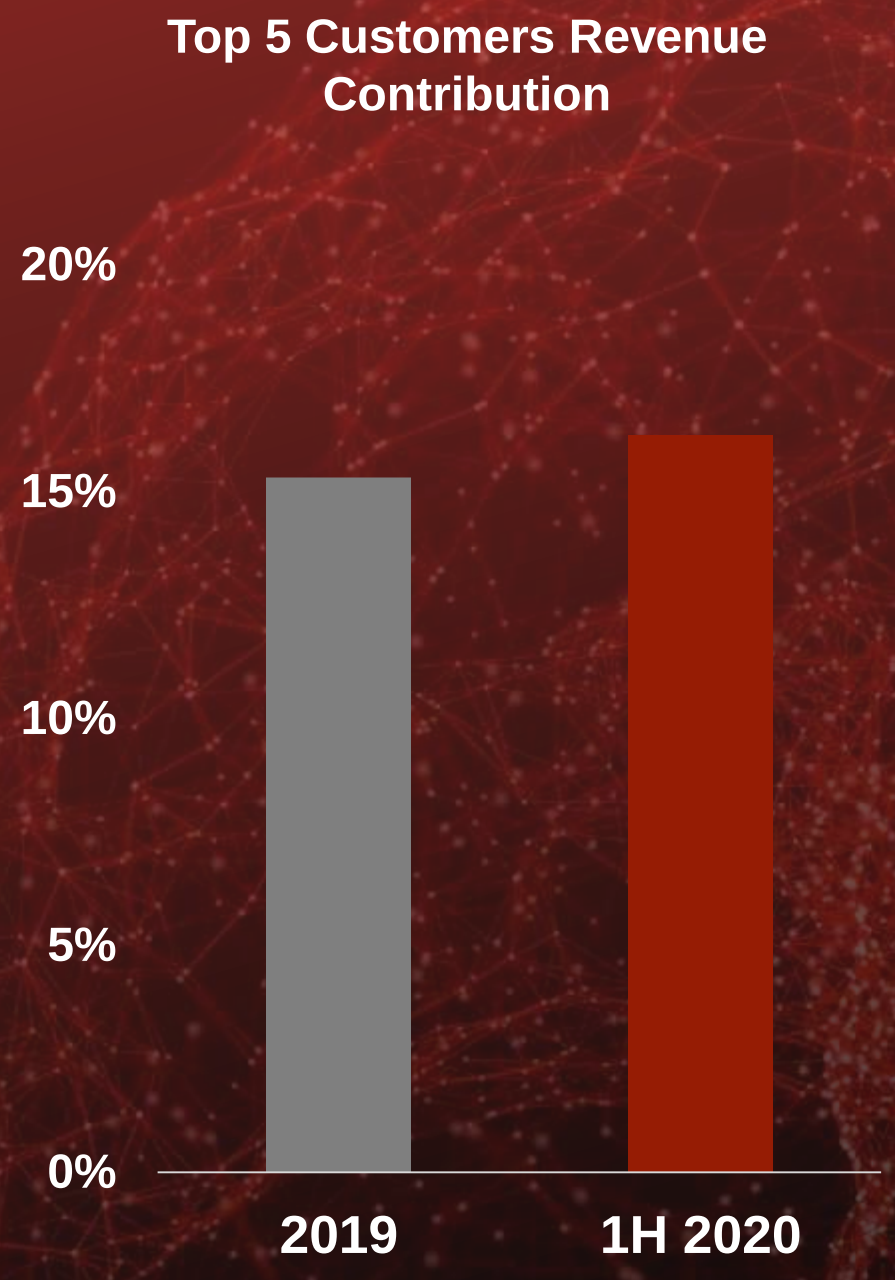
China Leads Market Recovery

- No single customer accounted for more than 10% of Group revenue
- Top 5 customers accounted for 16.25% of Group's 1H 2020 revenue
- Top 20 customers include:
  - World's leading Telecommunication and Information Technology provider
  - Leading High-Density Substrate makers
  - World's leading IDMs
  - Tier 1 OSATs, major OSATs in China
  - Major camera module makers
  - Top EMS providers
  - Leading automotive component suppliers
- Among Top 20 customers of Group:
  - 4 from SMT Solutions segment
  - 8 from both Semi Solutions & SMT Solutions segment

1H 2020 Revenue Breakdown by Application Markets



More Resilient in a Downturn with Multiple Application Markets Strategy



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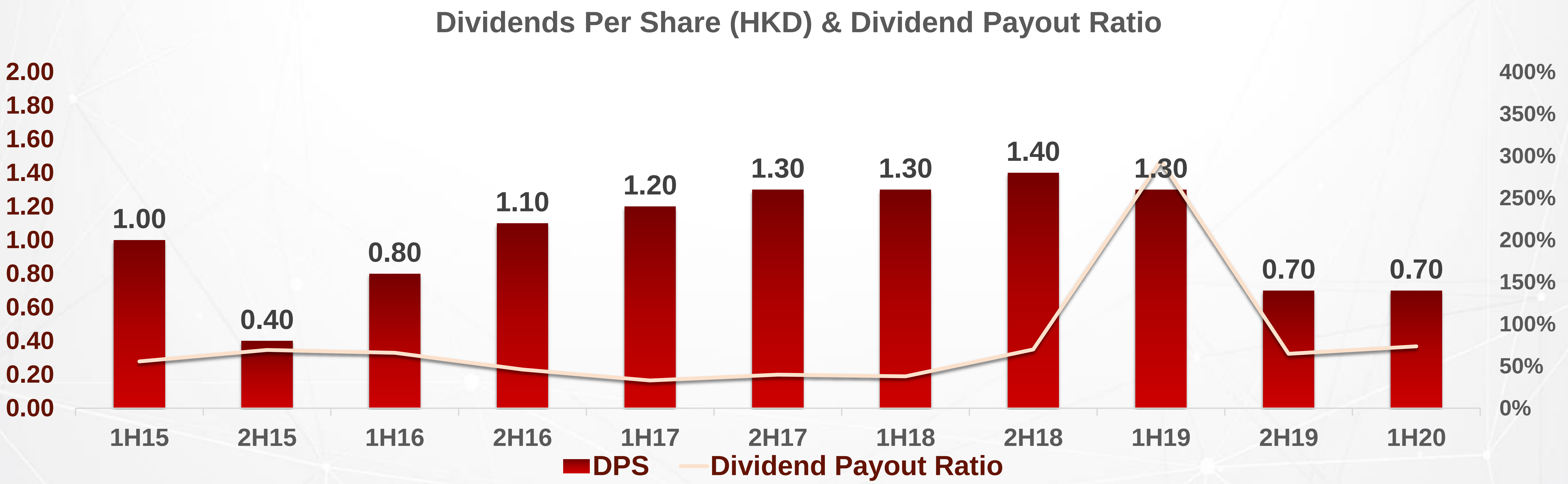
1H2020 Dividends



- Adopting a prudent stance in light of COVID-19 outbreak situation
- Dividend of HKD 0.70 for 1H20, representing a payout ratio of 74% for 1H20

New Lifestyle Norms Fast-tracking Digitalisation


‘Work from Home’ Initiatives by Companies Worldwide


Online “Live” Fitness Classes

“Zoom, Microsoft Teams usage are rocketing”
Marketwatch, April 2020

“First-Quarter Demand Picked Up on Laptop Orders”
Intel

“Apple and Google partner on COVID-19 contact tracing technology”
Apple, Google, April 2020

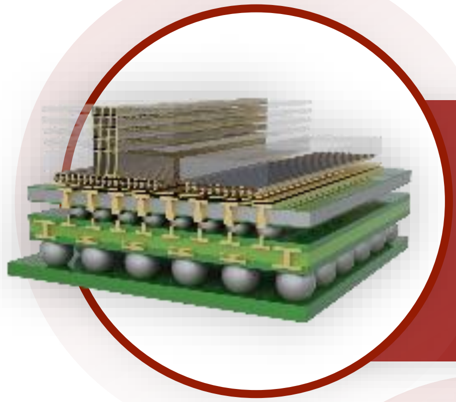

Home-based Learning adopted by schools


Harnessing Technology in Contact Tracing

Data-Centric Era will **spur Semiconductor Demand**

	Collect	**Transmit**	**Store**	**Analyse**	**Visualise**
	Camera, 3D Sensing, Industry IoT, Sensor, LIDAR	*5G, WiFi, LiFi*	*Big Data Centre, Cloud Computing, Memory*	*AI, TPU, Data Analytics, HPC*	*AR, VR, Micro LED, Mini LED*
ASMPT's Enabling Solutions	• CMOS Imaging Sensors • Active Alignment • Precision Die Attach	• Silicon Photonics • RF Filters • Wire Bonding • SAW Filters • BAW Filters • SMT Solutions • PVD	• Silicon Photonics • TCB • Wire Bonding • PLFO • Laser Dicing	• WLFO • PLFO • Pick & Place • Laser Grooving • TCB • PVD/ECD • Precision Die Attach • Heterogeneous Integration	• High Precision Die Attach • Mini/Micro LED Displays

Q2 2020 Growth Drivers For ASMPT



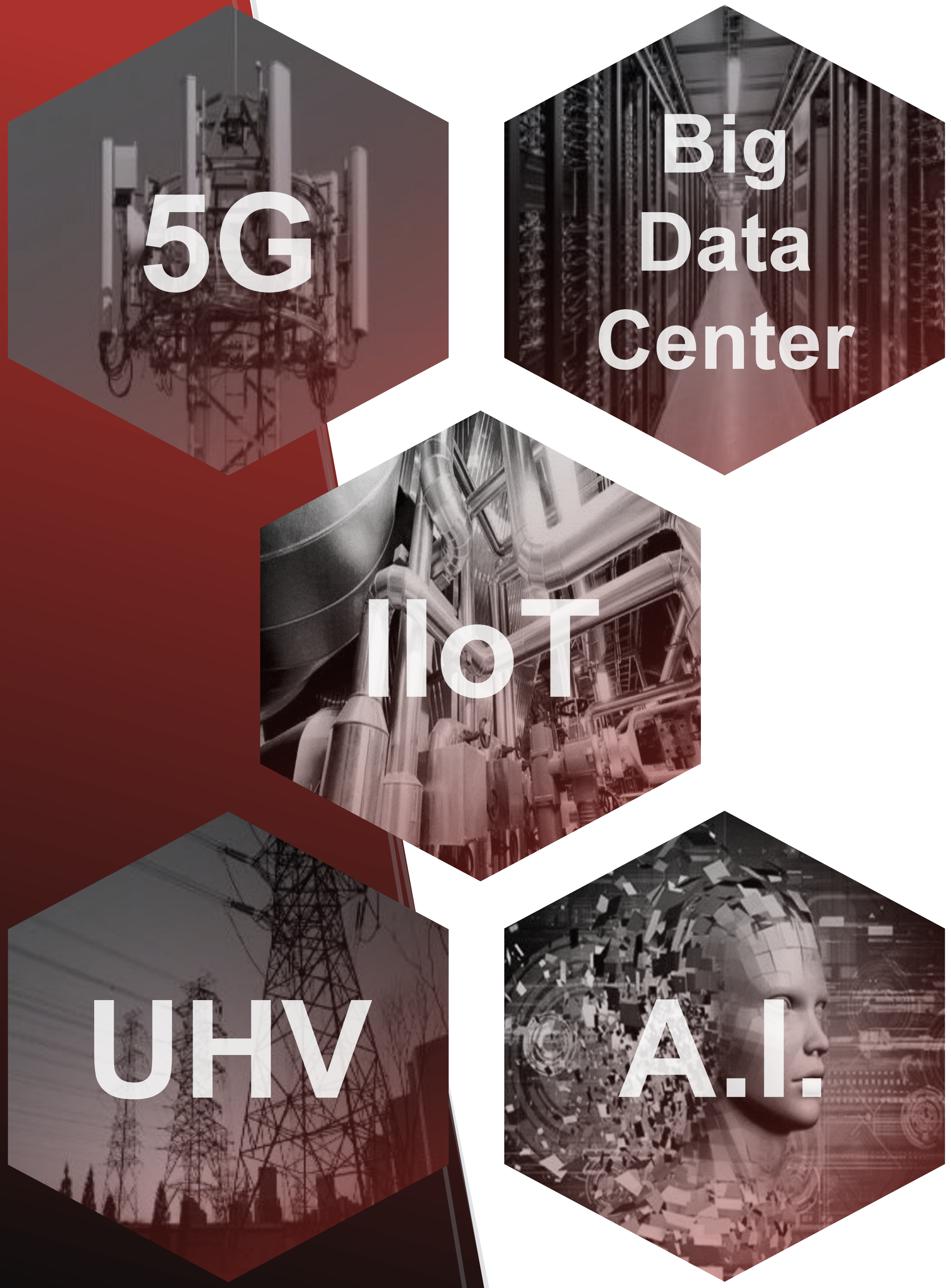
Advanced Packaging

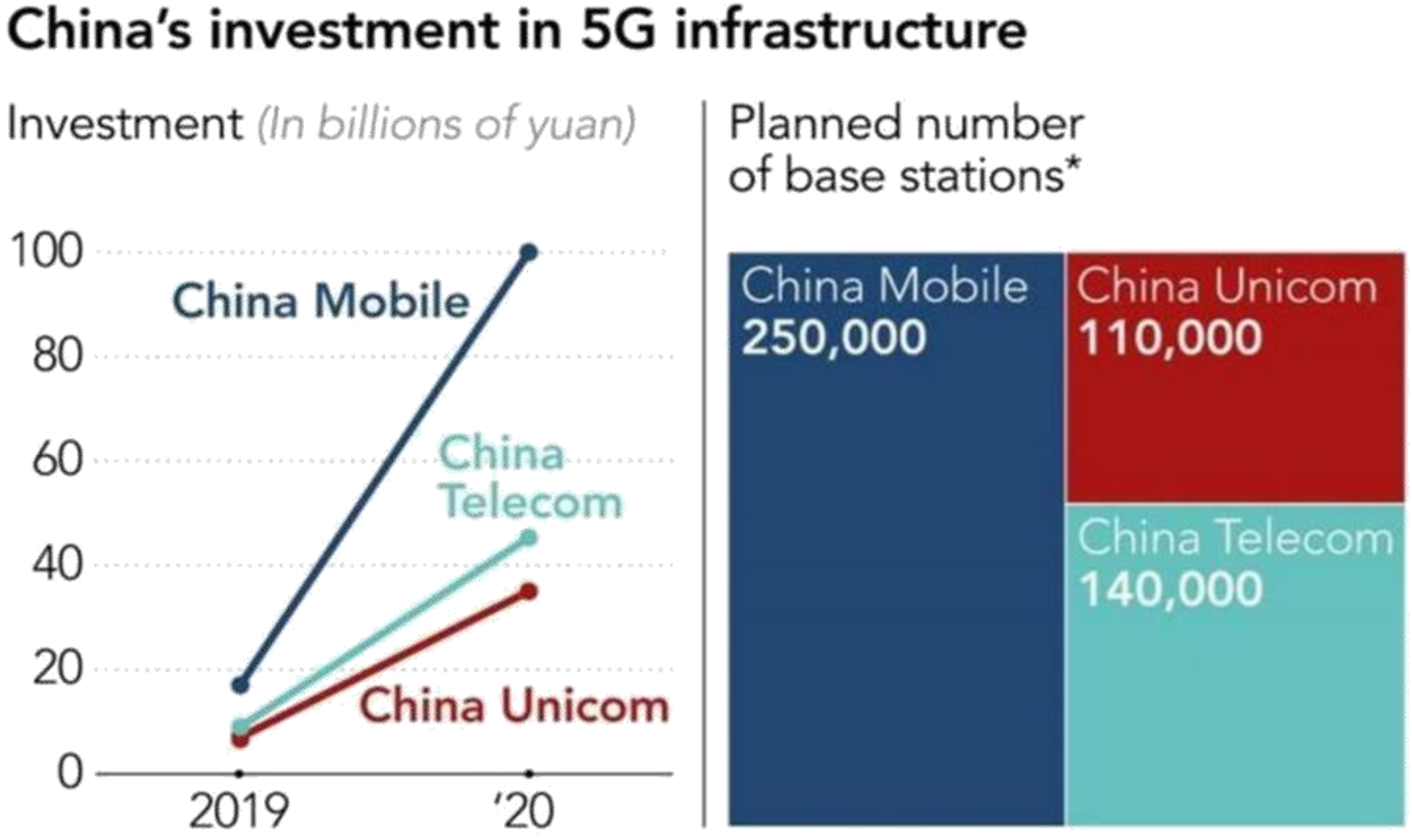
China Supply Chain Localisation

5G

Optoelectronics

Digital Acceleration Opportunities in China




China's investment in 5G infrastructure

Source: Trendforce and Nikkei Asian Review reporting

5G Will Transform the World Beyond Our Imagination

Infrastructure

2019-2025: 25-30mil
New 5G
Base Stations
Source: Topology Research Institute 2019

Big Data
Cloud Servers

"Power" Up
All Industries

Terminal

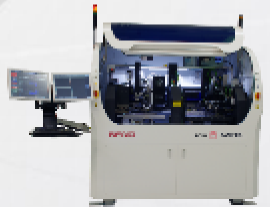
2023: 417mil
New 5G
Handsets
Source: IDC, 2019

Smart Consumer

50 MEMS & Sensors
per car
Automotive
Source: Bosch, 2019

5G

ASMPT Solutions for 5G:


Photonics Solutions


IC & Discrete Solutions


Image Sensor Solutions


Advanced Packaging


SMT Solutions


Power Solutions


Wafer Separation

Complete CIS Camera Assembly Solution

Market Leader for Unique In-line Solutions

SECURITY CHECK APPROVED

IDEALine™
(CMOS Image Sensor Solution)

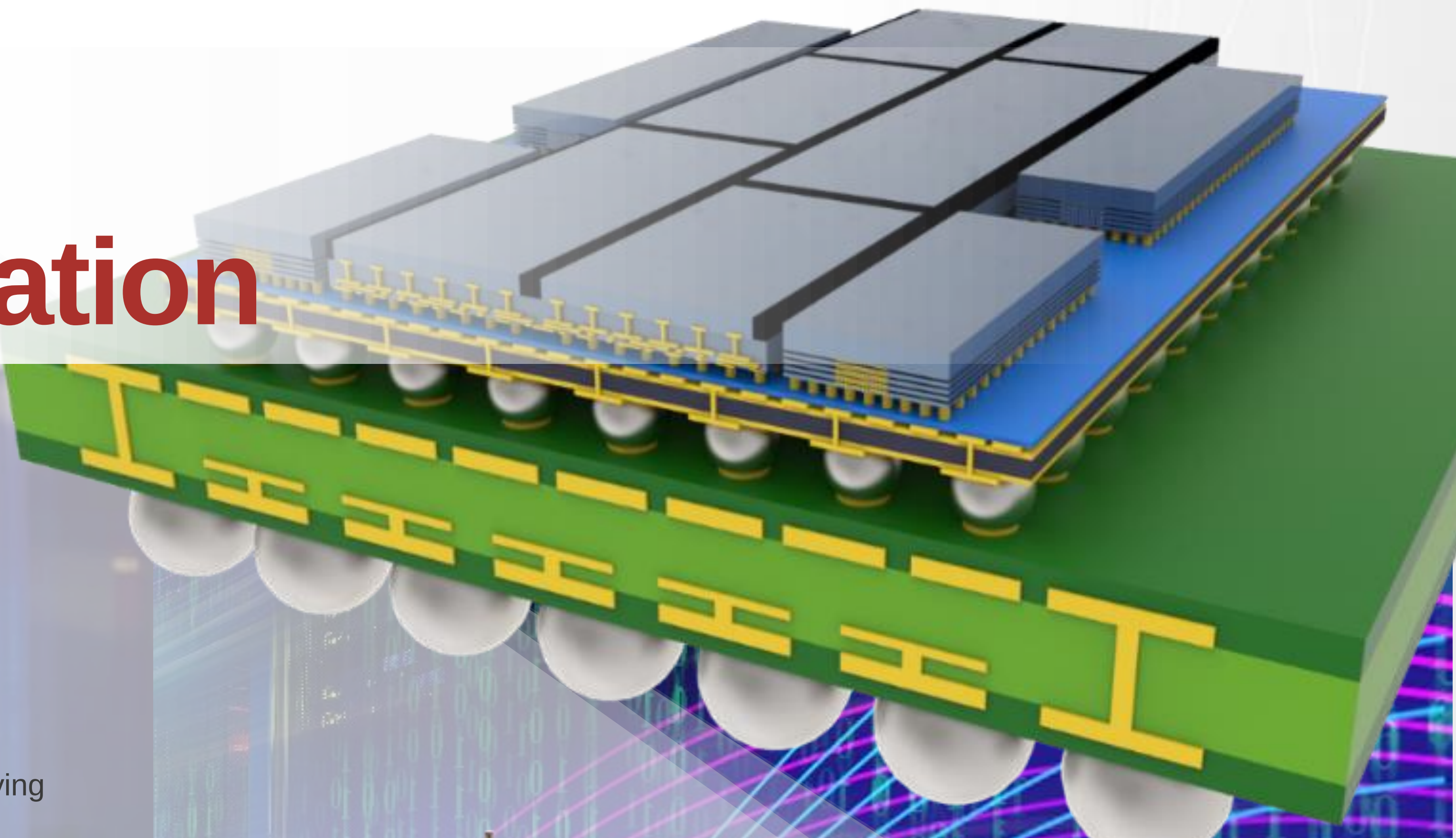
ACamLine™
(Automotive Camera Assembly Solution)

AUTOPIA FT
(Automatic Camera Testing System)

Smartphone Solutions

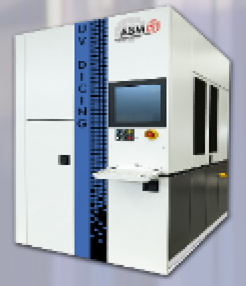
Automotive Solutions

Advanced Packaging
Enables Heterogeneous Integration

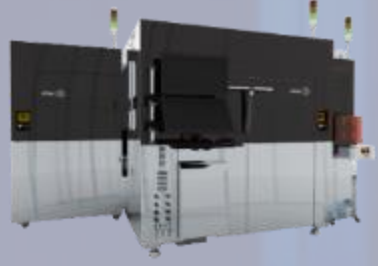


SIPLACE CA
Die Attach & SMT
Wafer & Panel Recon
IPD tool

NEXX
PVD | ECD
Bumping, TSV & RDL



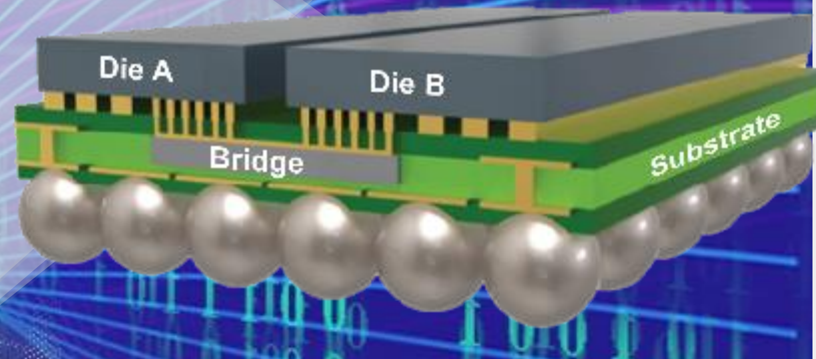
LASER 1205
Laser Separation
Wafer Dicing & Grooving



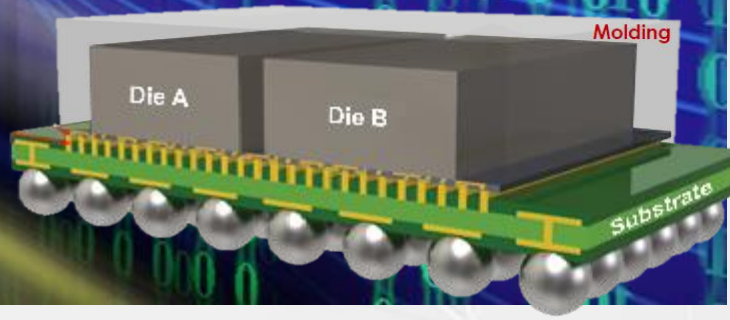
NUCLEUS XPM
HBM Bonder

NUCLEUS
Pick & Place
Wafer & Panel Level

ORCAS
Compression mold
Wafer & Panel Level



FIREBIRD
TCB, FLI



End Applications:

DATACENTRES
for HPC, Machine Learning

IoT ERA
Smart Wearables & Smart Machines (Factories)

AUTOMOTIVE
Sensors, Camera, Body Electronics, Safety Systems, Infotainment

GPU
for VR/AR & AI

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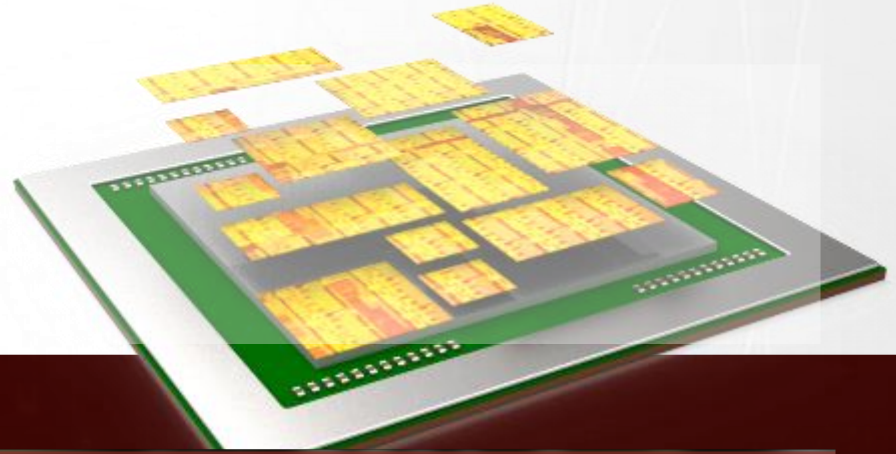
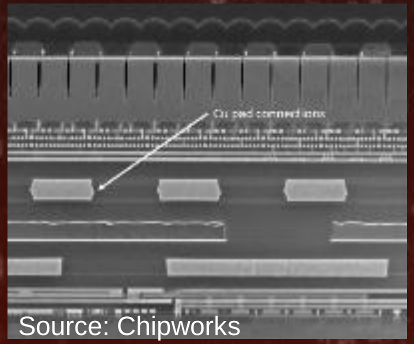
Hybrid Bonding Solution

Next Generation Heterogeneous Integration Technology

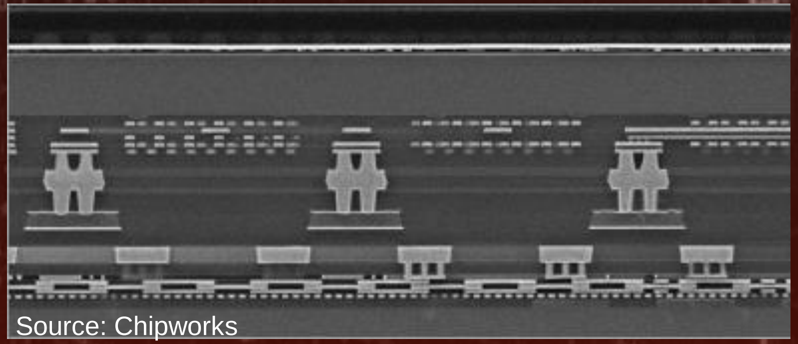


Bringing Heterogeneous Integration to the next level to enable high performance device, driving for future AI & HPC technology in a more cost effective way

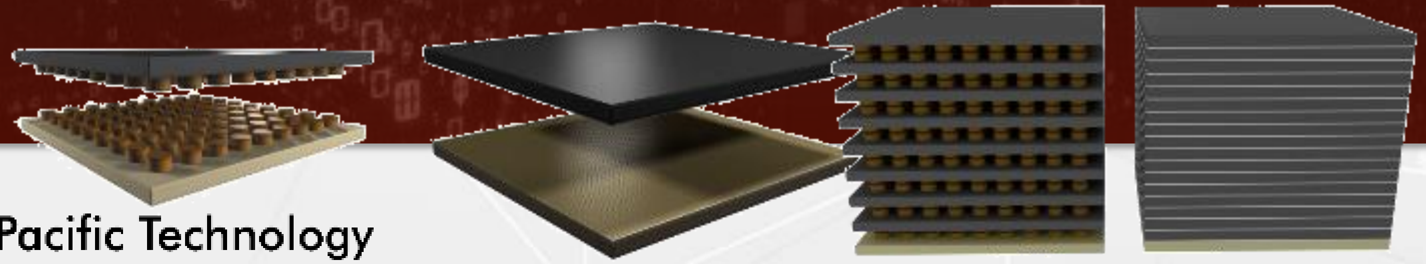
- Higher Interconnect density
  Interconnect density > 10^5/mm^2, with connecting pad size and pitch down below 5um
- Zero bond line with bump-less interconnect
  With direct Cu-Cu hybrid bonding
- Better signal integrity and thermal performance



Source: Chipworks



Source: Chipworks

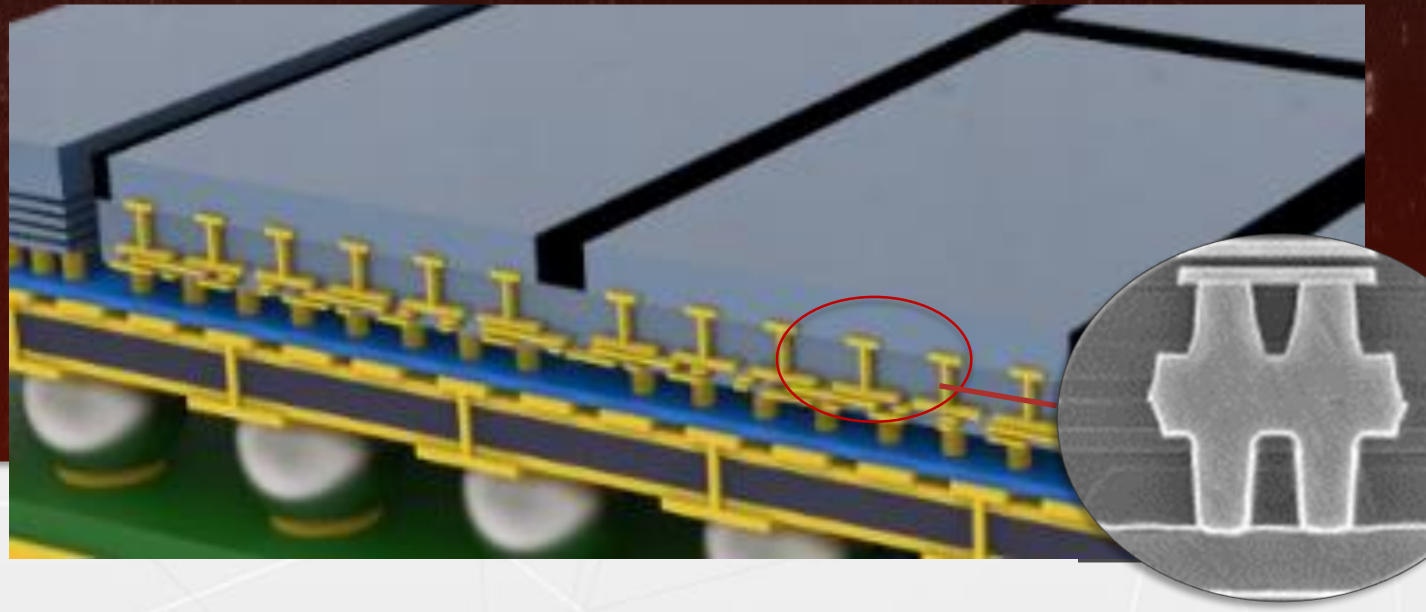


Source: Xperi

Source: Xperi

ASM Advanced Packaging Technology enables
Hybrid bonding solution for Heterogeneous Integration

- Ultra High Placement accuracy
  Bond accuracy +/-200nm
- Ultra High Cleanliness
- High Productivity
  CPH > 2K



Future Growth Drivers for OPTO Business

MiniLED

Medium to Large RGB / BLU Display

Market Size CAGR (2019 – 2025)

~ 35%

Market Size CAGR (2019 – 2025)

~ 131%

MicroLED

Small Gadget & Transparent Display

Fast Growing Applications

Source: LEDInside, Sep 2019

63% Automotive Display CAGR (2019 – 2025)

35% Digital Display CAGR (2019 – 2025)

31% Large Display CAGR (2019 – 2025)

118% Smartphone Display CAGR (2022 – 2025)

91% Wearable Display CAGR (2020 – 2025)

75% VR Display CAGR (2021 – 2025)

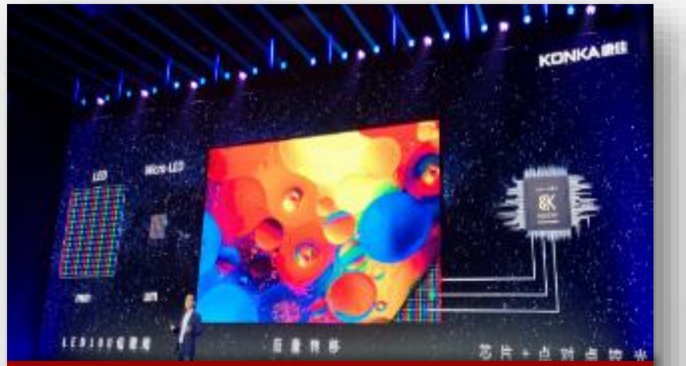
TCL
(TCL Conference - 2019)

LEYARD
(InfoComm - 2019)

RitDisplay + PlayNitride
(Touch Taiwan - 2019)

TIANMA
(SID - 2019)

CEDAR ELECTRONICS
(InfoComm - 2019)



KONKA
(KONKA Conference - 2019)

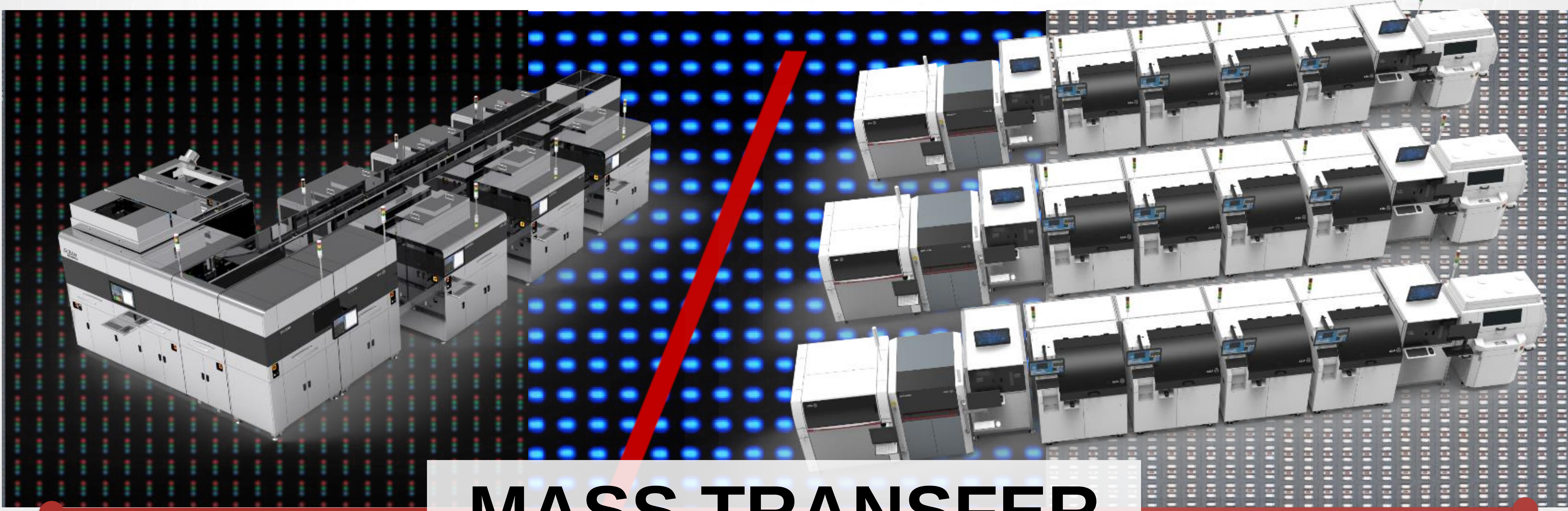
AUO
(Touch Taiwan - 2019)

Samsung
(CES - 2019)

Source: Photos of displays from various conferences

Unique and Ready for Mass Production

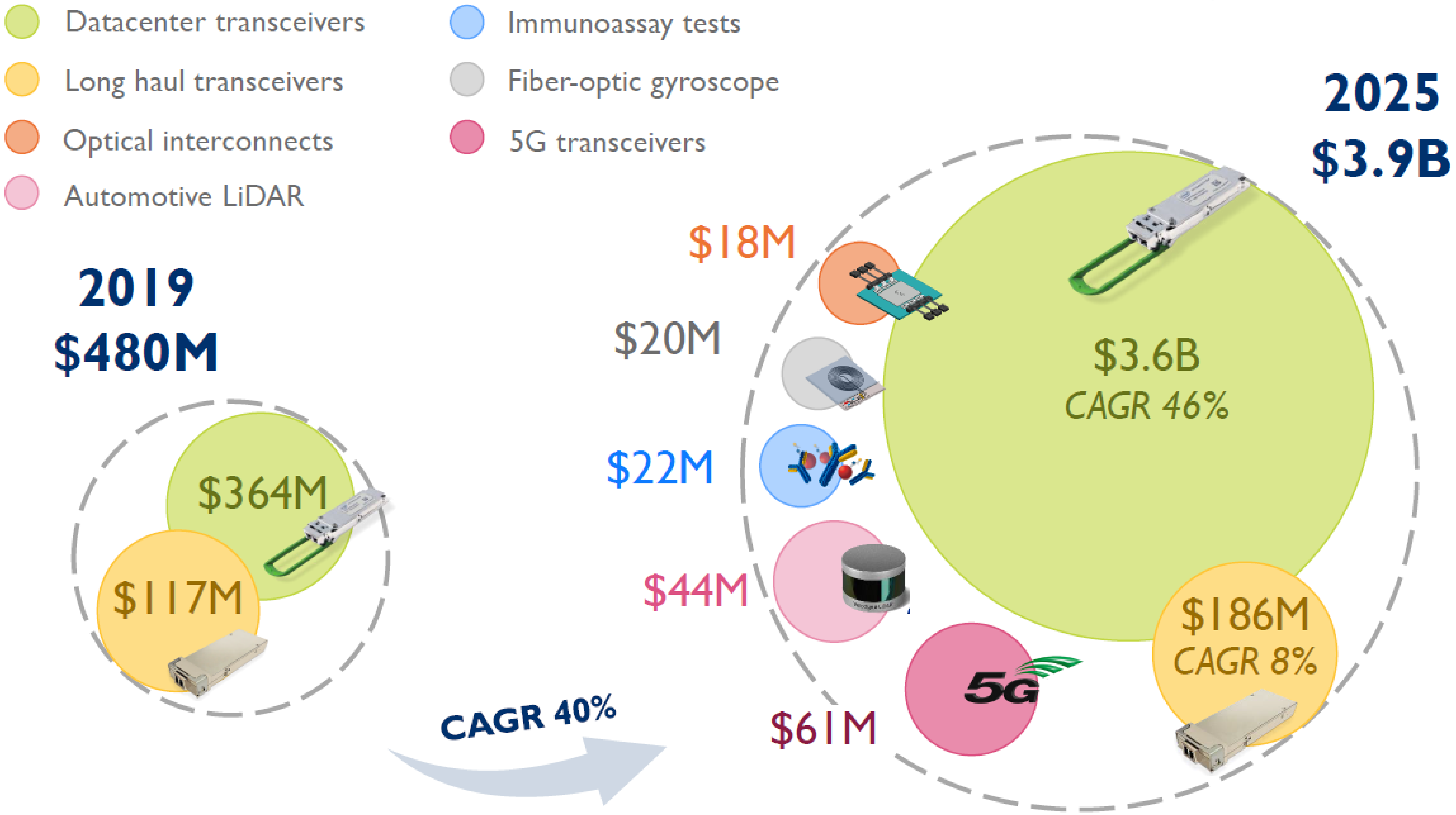
Mini & Micro LED Solution



MASS TRANSFER

Up to 300,000 chips per bonding cycle

Booming Applications in Photonics Market



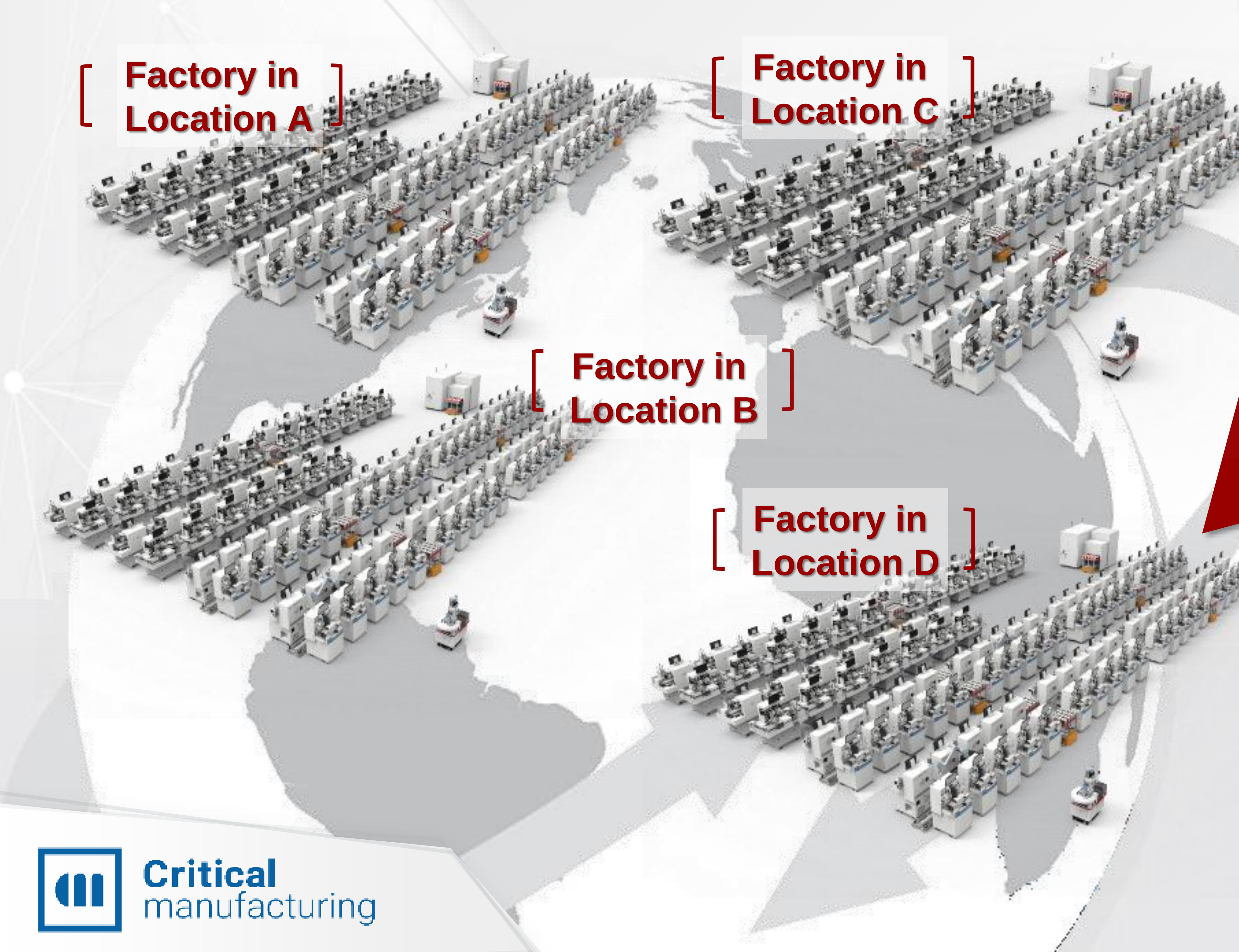
Si Photonics Market Size (USD'M)

Source: Yole, 2020

ASM AMICRA

2018 THOMSON REUTERS TOP100 GLOBAL TECH LEADER

IIoT & Smart Manufacturing
Powered Up by 5G Network



Industrial IoT

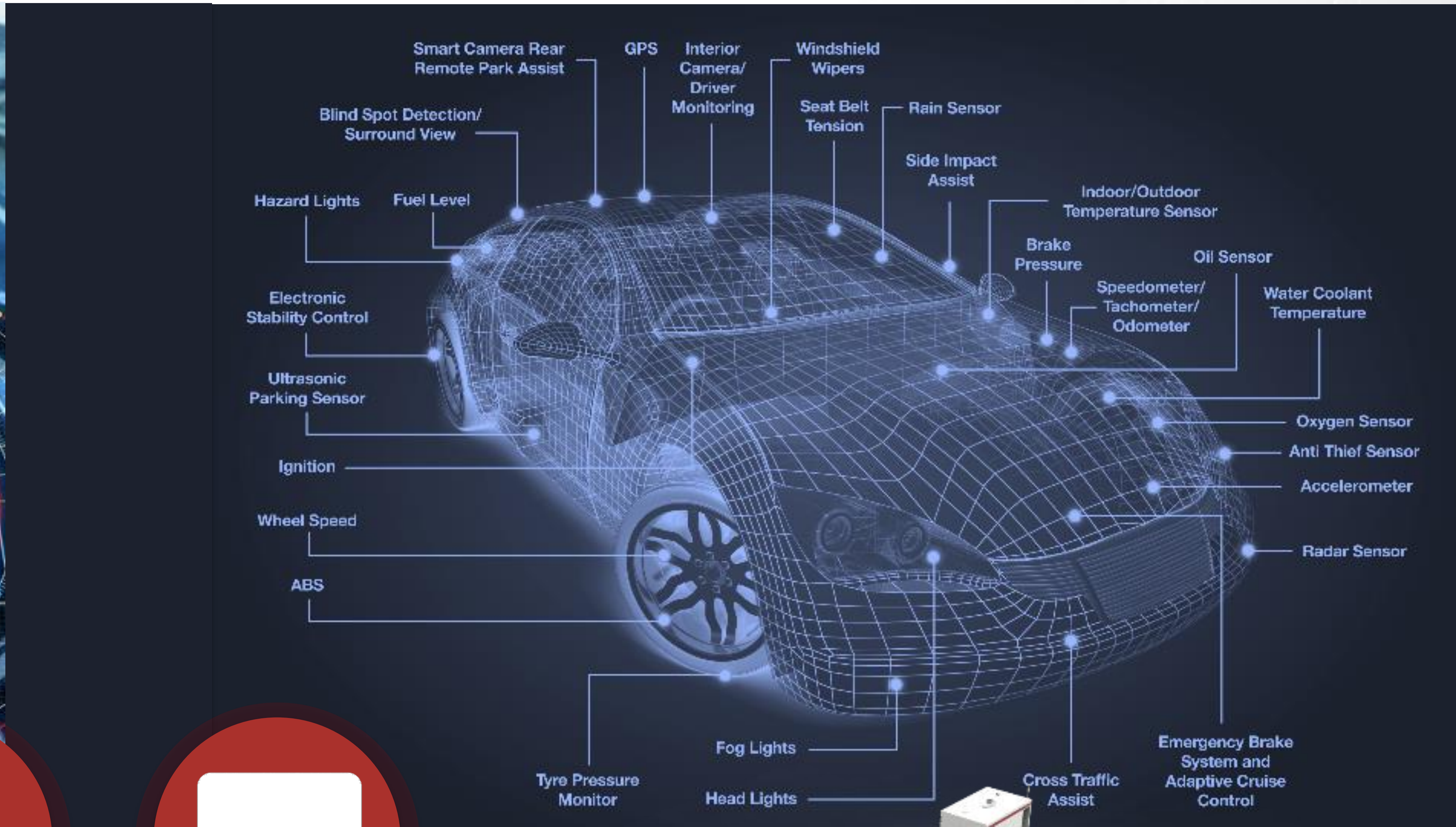
~ 24%

CAGR (2019 – 2023)

Source: Marketwatch,
Sep 2019

Critical
manufacturing

Digital Technologies Enabling the Autonomous Driving Experience



5G NETWORK

MEMS

POWER

DISPLAY

ASM Pacific Technology

2018 THOMSON REUTERS
TOP100
GLOBAL TECH LEADER

Outlook

Outlook

- Global full year 2020 growth projections revised downwards from -3.0% to -4.9% by IMF during June 2020 review.
- Threat from a second wave of COVID-19 infection and continued fallout from the worsening US-China tension remains a global concern for 2H2020.
- In light of these uncertainties, no guidance on Q3 Bookings will be provided.

Q3 Group Billings Guidance

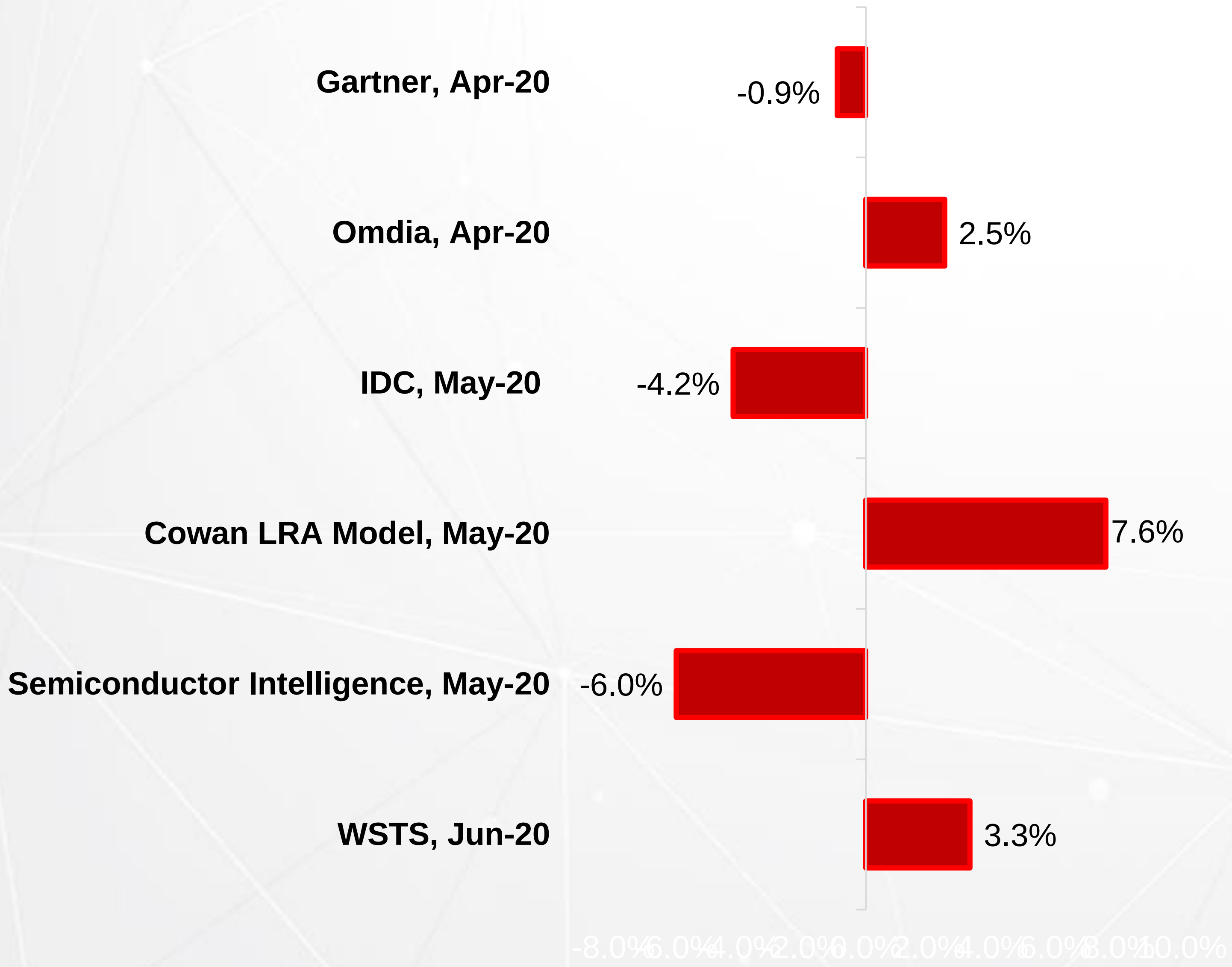
- US$480m – US$560m
- Subdued demand for Automotive and weakness in Eurozone

Longer Term Outlook

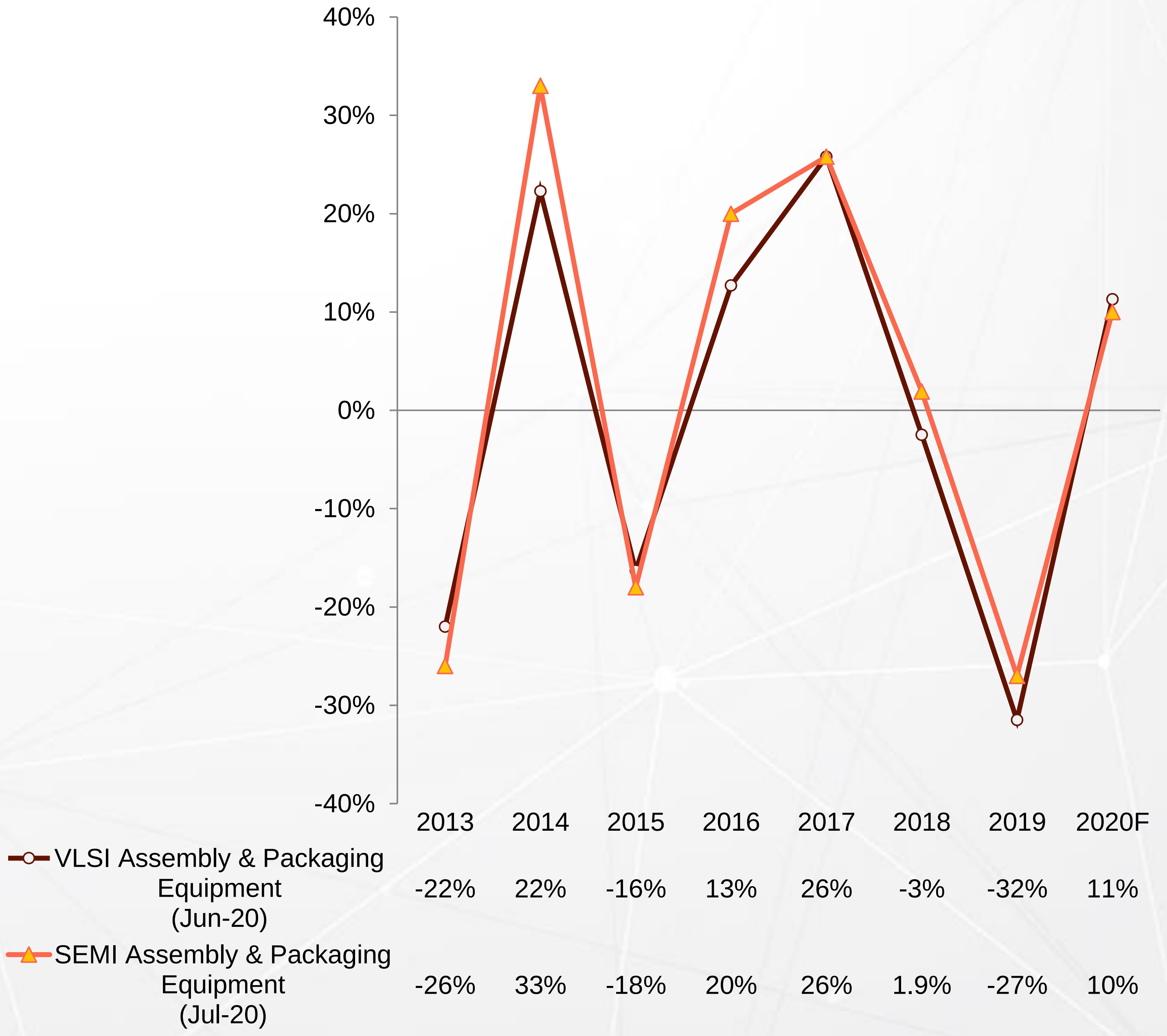
- Supply chain localization and deployment of 5G infrastructure opening up new market opportunities in:
  - AP, Silicon Photonics, IIoT, mini and micro LED solutions, Power semiconductor and Industry 4.0

Industry Growth Forecast (2020)

Semiconductor Industry



Forecast Global Assembly & Packaging Equipment Market



	2013	2014	2015	2016	2017	2018	2019	2020F
VLSI Assembly & Packaging Equipment (Jun-20)	-22%	22%	-16%	13%	26%	-3%	-32%	11%
SEMI Assembly & Packaging Equipment (Jul-20)	-26%	33%	-18%	20%	26%	1.9%	-27%	10%

Recent Awards & Recognition

Latest

VLSIresearch 10 BEST SUPPLIERS Customer Satisfaction 2020

10 BEST Segment	Rank	10 BEST CHIP MAKING EQUIPMENT SUPPLIERS OF 2020	Rating	Stars
LARGE	1	ADVANTEST	9.50	★★★★★
	2	TERADYNE	9.48	★★★★★
	3	ASML	9.31	★★★★★
	4	ASM Pacific Technology	8.92	★★★★½
	5	KE KOKUSAI ELECTRIC	8.35	★★★★
	6	TEL TOKYO ELECTRON	8.34	★★★★
	7	Lam RESEARCH	8.21	★★★★
	8	APPLIED MATERIALS	8.00	★★★★
	9	Hitachi High-Tech	7.64	★★★½
FOCUSED	1	Plasma-Therm	9.02	★★★★★
	2	FORMFACTOR	8.91	★★★★½
	3	EVG	8.86	★★★★½
	4	Cohu	8.82	★★★★½
	5	axcelis	8.21	★★★★
	6	Canon	7.91	★★★½
	7	Nikon	7.58	★★★½
	8	SUSS MicroTec	7.25	★★★

Source: VLSIresearch
css_10BEST_v20.05

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VLSIresearch THE BEST SUPPLIERS Customer Satisfaction 2020

WHAT THE BEST SUPPLIERS OF 2020 ARE BEST AT

ADVANTEST	Recommend Supplier Trust In Supplier	APPLIED MATERIALS	Technical Leadership Quality of Results
ASM Pacific Technology	Field Engineering Support Partnering and Support After Sales	ASML	Technical Leadership Recommend Supplier
axcelis	Field Engineering Support Partnering	Canon	Overall Value Partnering
Cohu	Recommend Supplier Partnering	EDWARDS	Quality of Results Partnering
EVG	Partnering Recommend Supplier	FORMFACTOR	Technical Leadership Trust In Supplier
Hitachi High-Tech	Uptime Product Performance and Quality of Results	JEM JAPAN ELECTRONIC MATERIALS	Partnering Support After Sales
KE KOKUSAI ELECTRIC	Support After Sales Uptime	Lam RESEARCH	Technical Leadership Recommend Supplier
Nidec SV TCL	Application Support Recommend Supplier	Nikon	Overall Value Support After Sales
Plasma-Therm	Spares Support Field Engineering Support	SUSS MicroTec	Application Support Quality of Results
TECHNOPROBE Wafer Probing Technologies	Field Engineering Support Application Support	TERADYNE	Recommend Supplier Trust In Supplier
TEL TOKYO ELECTRON	Product Performance Recommend Supplier		

Source: VLSIresearch Doc: css_THEBEST_v20.06

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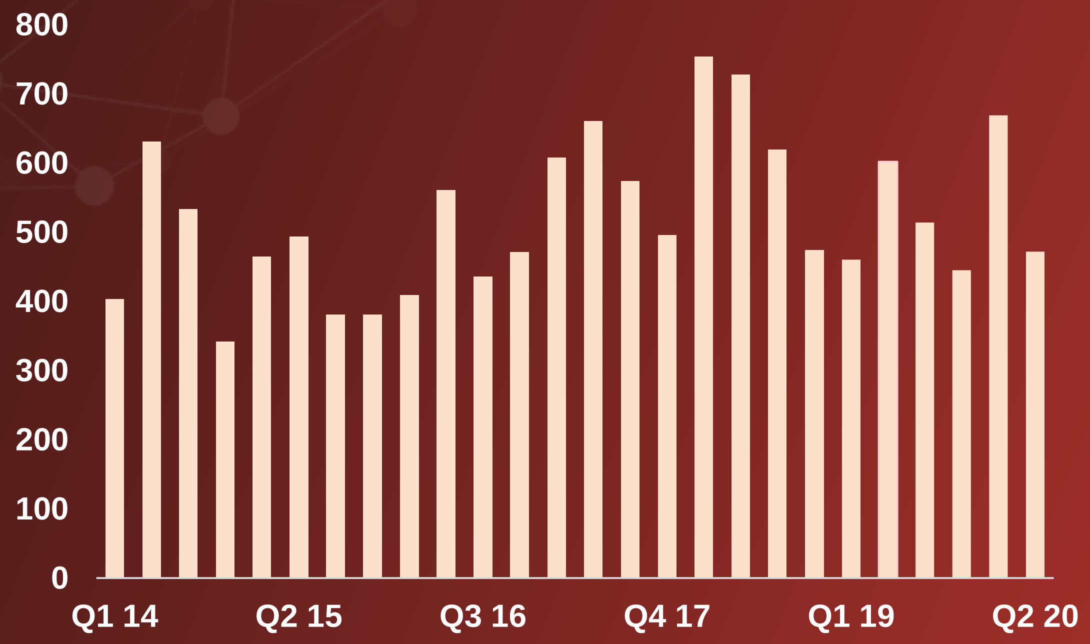
2018 THOMSON REUTERS
TOP100
GLOBAL TECH LEADER

Q2/1H 2020
Financial Highlights

Q2/1H 2020 Group Bookings

QoQ Growth:
-29.4%

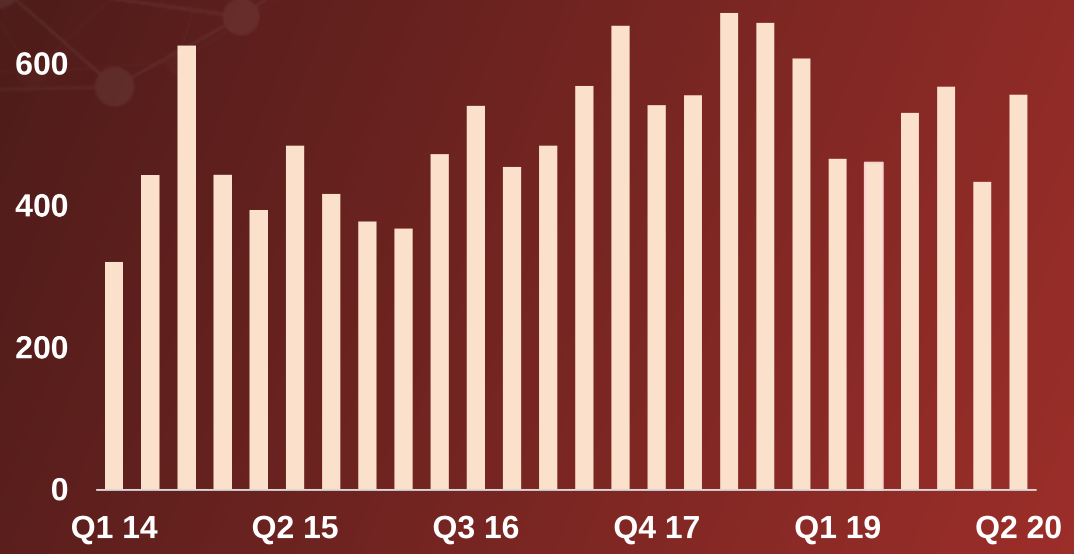


Quarterly Group Bookings
(USD'M)

	Q2 2020 Bookings			1H 2020 Bookings		
	USD	**YoY**	**QoQ**	**USD**	**YoY**	**HoH**
Group	**472m**	**-21.6%**	**-29.4%**	**1,141m**	**+7.4%**	**+19.0%**
Semi Solutions Segment	**227m**	**-8.1%**	**-26.7%**	**537m**	**+14.2%**	**+21.7%**
Materials Segment	**78m**	**+32.7%**	**-11.8%**	**167m**	**+59.3%**	**+25.2%**
SMT Solutions Segment	**167m**	**-43.7%**	**-38.4%**	**437m**	**-10.3%**	**+13.7%**

Q2/1H 2020 Group Billings

QoQ Growth:
+27.8%



Quarterly Group Billings (USD'M)

	Q2 2020 Billings			*1H 2020 Billings*		
	USD	**YoY**	**QoQ**	**USD**	**YoY**	**HoH**
Group	**557m**	**+19.5%**	**+27.8%**	**992m**	**+5.9%**	**-10.5%**
Semi Solutions Segment	**279m**	**+33.8%**	**+43.0%**	**473m**	**+16.6%**	**-4.5%**
Materials Segment	**74m**	**+28.2%**	**+43.2%**	**126m**	**+15.6%**	**-3.2%**
SMT Solutions Segment	**204m**	**+2.2%**	**+8.0%**	**393m**	**-6.9%**	**-18.7%**

Q2/1H 2020 Group Financial Highlights

	Q2 2020	Q2 2020		1H 2020	1H 2020	
		YoY	QoQ		YoY	HoH
Bookings (USD)	**472m**	**-21.6%**	**-29.4%**	**1,141m**	**+7.4%**	**+19.0%**
Revenue (USD)	**557m**	**+19.5%**	**+27.8%**	**992m**	**+5.9%**	**-10.5%**
Gross Margin	**35.2%**	**-54 bps**	**+169 bps**	**34.5%**	**-34 bps**	**-29 bps**
EBIT (HKD)	**457m**	**+107.4%**	**+269.6%**	**581m**	**+20.0%**	**-14.9%**
Net Profit (HKD)	**365m**	**+421.8%**	**+1,341.5%**	**391m**	**+119.2%**	**-12.0%**
Net Profit Margin	**8.5%**	**+652 bps**	**+771 bps**	**5.1%**	**+262 bps**	**-9 bps**

Q2/1H 2020 Segment Results – Semiconductor Solutions

	Q2 2020			*1H 2020*		
	Amount	**YoY**	**QoQ**	**Amount**	**YoY**	**HoH**
Bookings (USD)	**227m**	**-8.1%**	**-26.7%**	**537m**	**+14.2%**	**+21.7%**
Billings (USD)	**279m**	**+33.8%**	**+43.0%**	**473m**	**+16.6%**	**-4.5%**
Gross Margin	**42.9%**	**+211 bps**	**+162 bps**	**42.2%**	**+219 bps**	**+16 bps**
Segment Profit (HKD)	**336m**	**+404.3%**	**+297.2%**	**420m**	**+251.8%**	**+17.6%**
Segment Profit Margin	**15.5%**	**+1,140 bps**	**+993 bps**	**11.4%**	**+764 bps**	**+215 bps**

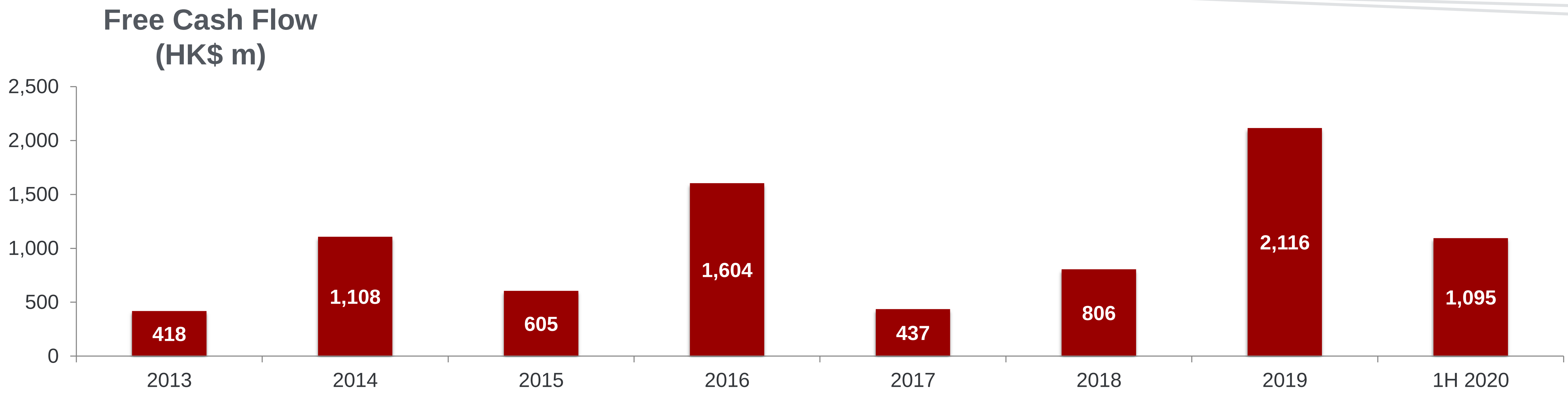
Q2/1H 2020 Segment Results – Materials

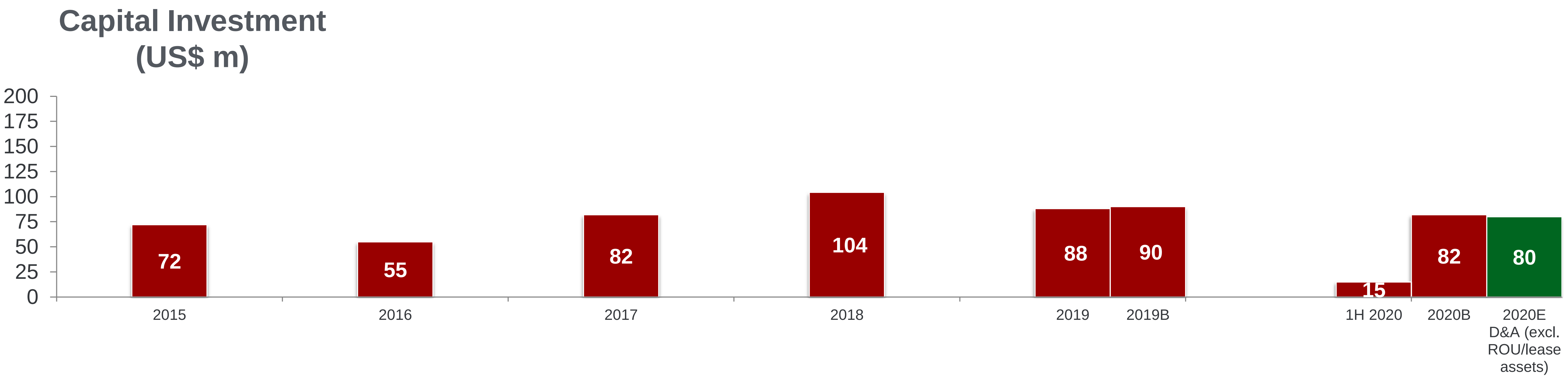
	Q2 2020			*1H 2020*		
	Amount	**YoY**	**QoQ**	**Amount**	**YoY**	**HoH**
Bookings (USD)	**78m**	**+32.7%**	**-11.8%**	**167m**	**+59.3%**	**+25.2%**
Billings (USD)	**74m**	**+28.2%**	**+43.2%**	**126m**	**+15.6%**	**-3.2%**
Gross Margin	**16.9%**	**+546 bps**	**+838 bps**	**13.5%**	**+250 bps**	**+409 bps**
Segment Profit (HKD)	**58m**	**+193.7%**	**+266.6%**	**74m**	**+144.4%**	**+163.4%**
Segment Profit Margin	**10.1%**	**+569 bps**	**+616 bps**	**7.6%**	**+399 bps**	**+479 bps**

Q2/1H 2020 Segment Results – SMT Solutions

	Q2 2020			*1H 2020*		
	Amount	**YoY**	**QoQ**	**Amount**	**YoY**	**HoH**
Bookings (USD)	**167m**	**-43.7%**	**-38.4%**	**437m**	**-10.3%**	**+13.7%**
Billings (USD)	**204m**	**+2.2%**	**+8.0%**	**393m**	**-6.9%**	**-18.7%**
Gross Margin	**31.3%**	**-616 bps**	**-101 bps**	**31.8%**	**-409 bps**	**-225 bps**
Segment Profit (HKD)	**159m**	**-24.0%**	**+25.5%**	**285m**	**-32.5%**	**-43.5%**
Segment Profit Margin	**10.0%**	**-346 bps**	**+140 bps**	**9.3%**	**-354 bps**	**-410 bps**

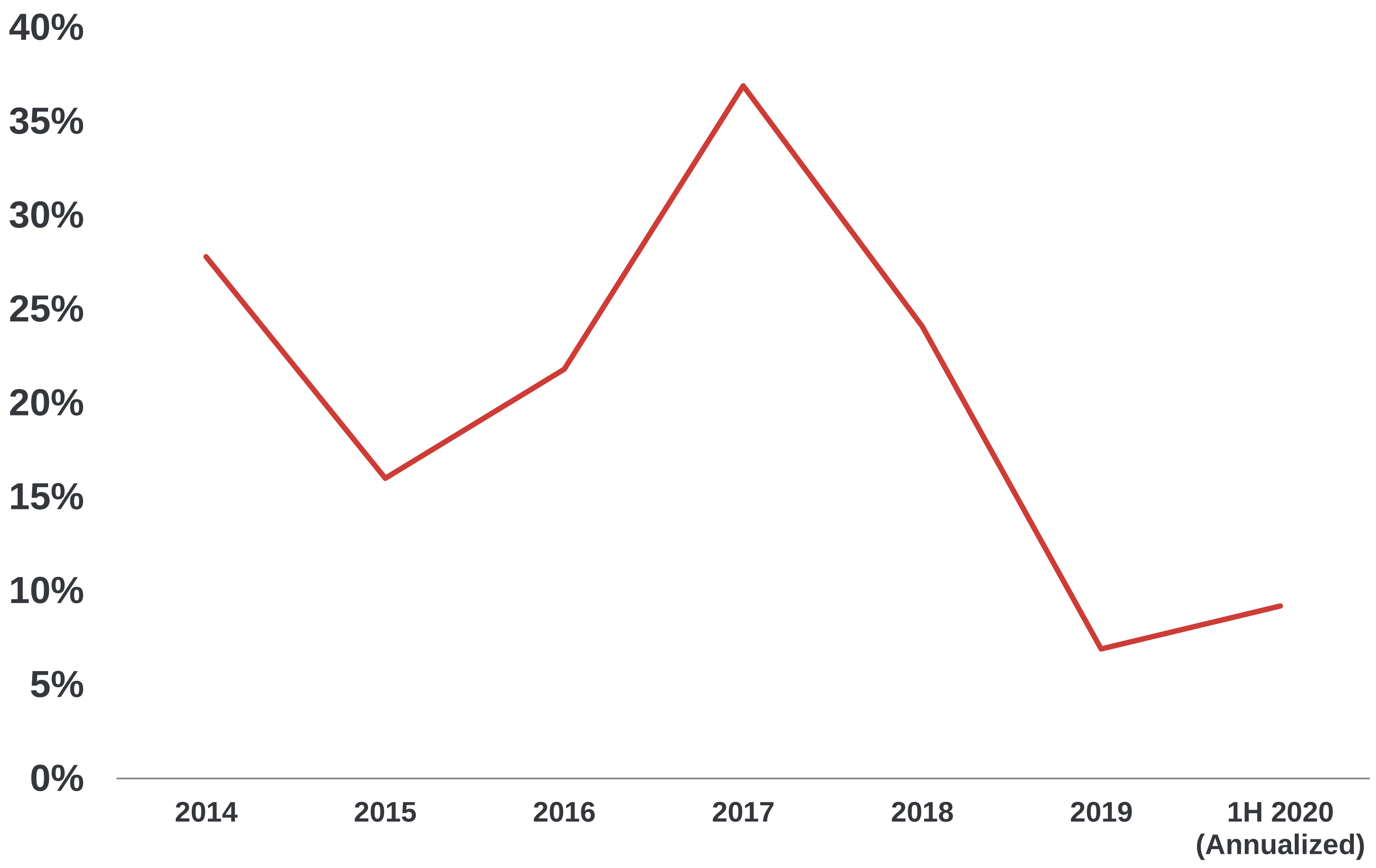
Free Cash Flow and Capital Investment



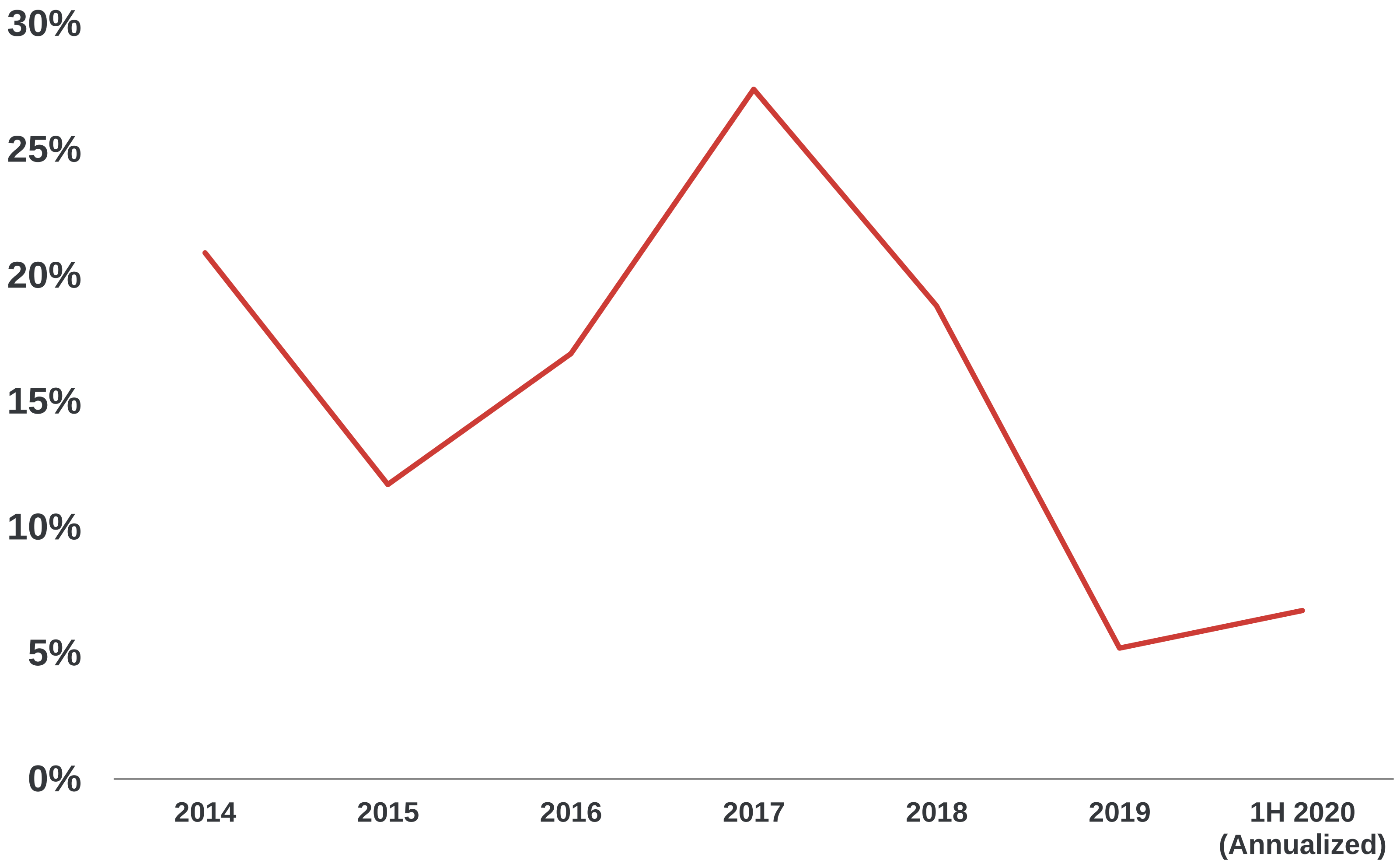


Financial Metrics

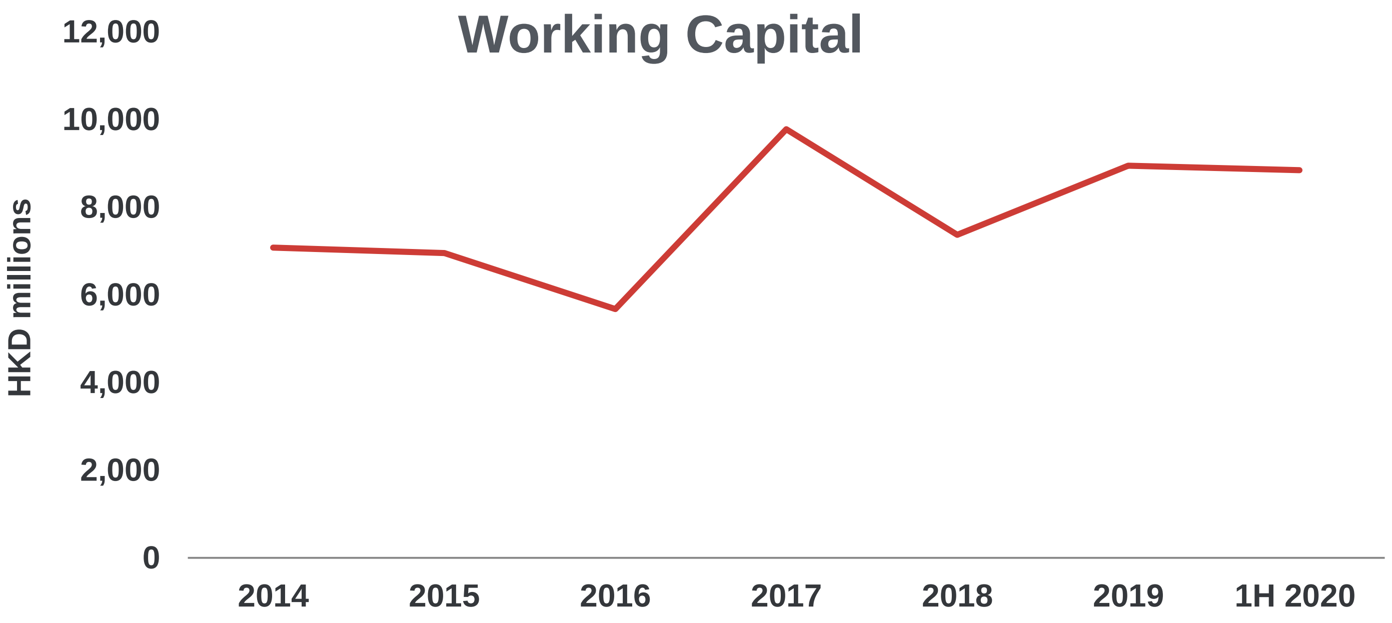
Return on Invested Capital (ROIC)

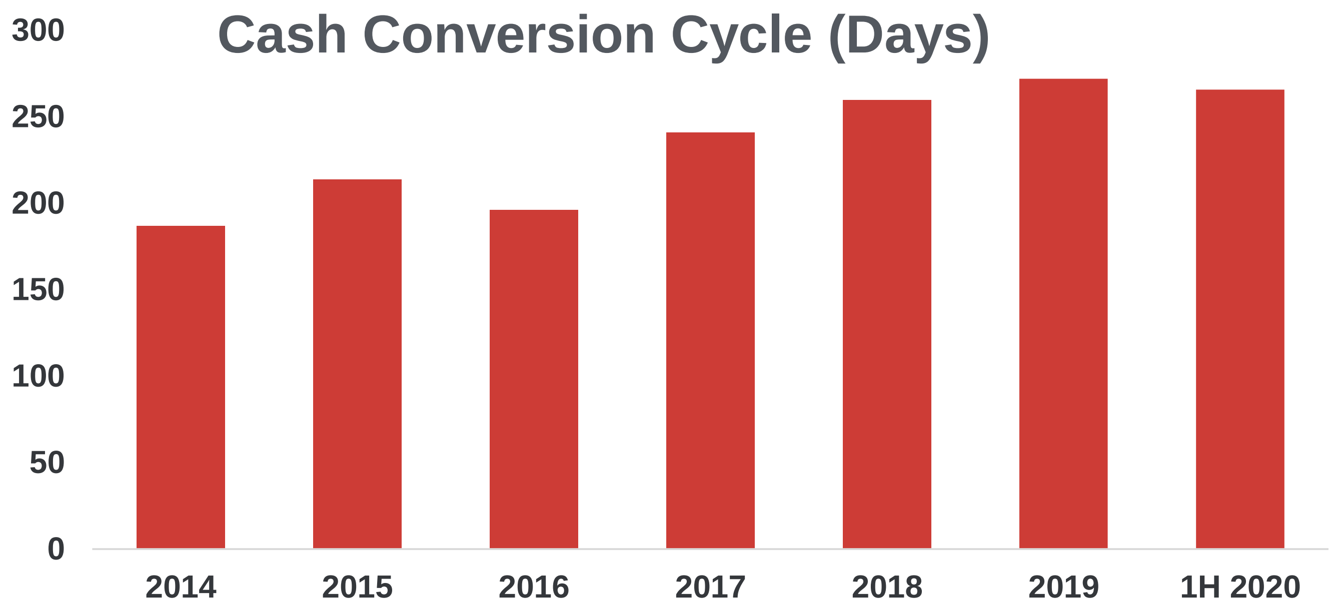


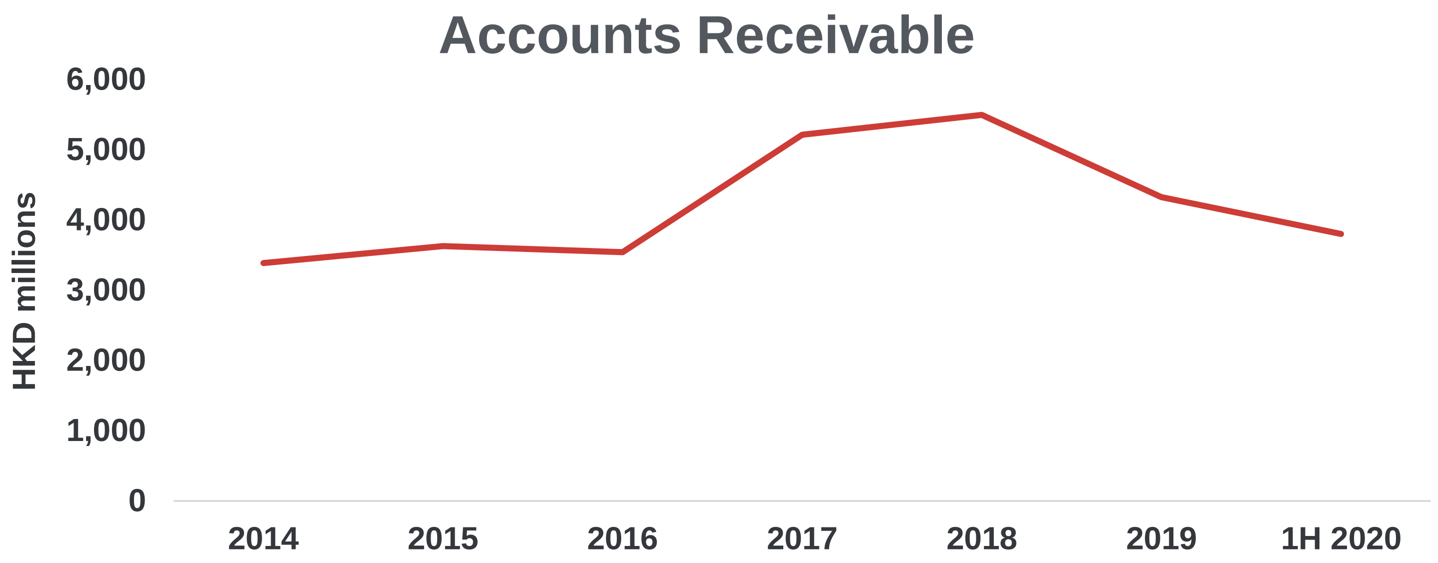
Return on Equity (ROE)

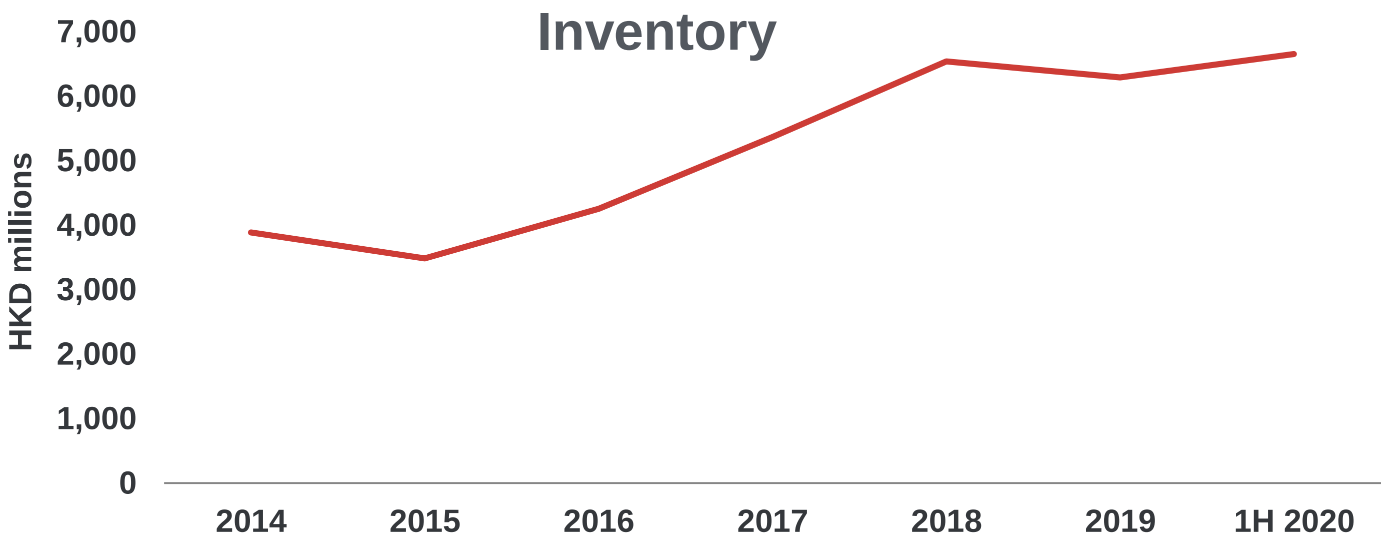


Working Capital Management


Working Capital


Cash Conversion Cycle (Days)


Accounts Receivable


Inventory

ASM Pacific Technology

ENABLING THE DIGITAL WORLD